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12-Bit, 100-MSPS, 8-Channel Analog-to-Digital Converter

Check for Samples: ADS5295

FEATURES

- Maximum Sample Rate: 100 MSPS
- **Designed for Low Power:**
 - 80 mW per channel at 100 MSPS
- SNR: 70.6 dBFS
- SFDR: 85 dBc at 10 MHz, 100 MSPS
- Serial LVDS ADC Data Outputs:
 - One- or Two-Wire Serialized LVDS Outputs per Channel
 - One-Wire Interface: Up to 80 MSPS Sample Rate
 - Two-Wire Interface: Up to 100 MSPS Sample Rate
- **Digital Processing Block:**
 - Programmable FIR Decimation Filter and **Oversampling to Minimize Harmonic** Interference
 - Programmable IIR High-Pass Filter to **Minimize DC Offset**
 - Programmable Digital Gain: 0 dB to 12 dB
- Low-Frequency Noise Suppression Mode
- **Programmable Mapping Between ADC Input Channels and LVDS Output Pins**
- **Channel Averaging Mode**
- Variety of LVDS Test Patterns to Verify • Data Capture by FPGA or Receiver
- Package: 12-mm × 12-mm QFP-80

APPLICATIONS

- Ultrasound Imaging
- **Communication Applications**
- Multichannel Data Acquisition

DESCRIPTION

The ADS5295 is a low-power, 12-bit, 100-MSPS, 8channel analog-to-digital converter (ADC). Low power consumption and integration of multiple channels in a compact package make the device attractive for very high channel count data acquisition systems.

Serial low-voltage differential signaling (LVDS) outputs reduce the number of interface lines and enable high system integration. The ADC digital data can be output over one or two wires of LVDS pins per channel. At high sample rates, the two-wire interface helps keep the serial data rate low, allowing low-cost field-programmable gate array (FPGA)-based receivers to be used.

The device integrates an internal reference trimmed accurately match across devices. to Best performance is expected to be achieved through the internal reference mode. However, the device can be driven with external references as well.

Several digital functions that are commonly used in systems are included in the device. These functions include a low-frequency suppression mode, digital filtering options, and programmable mapping.

For low input frequency applications, the lowfrequency noise suppression mode enables noise suppression at low frequencies and improves signalto-noise ratio (SNR) in the 1-MHz band near dc by approximately 3 dB. Digital filtering options include low-pass, high-pass, and band-pass digital filters, as well as dc offset removal filters. The device also provides programmable mapping of the LVDS output pins and analog input channels. For applications where the 12-bit ADC SNR is not required, the ADS5295 can be configured as an 8-channel, 10-bit ADC with 10x LVDS serialization to reduce the output data rate.

The device is available in a 12-mm × 12-mm QFP-80 package. The ADS5295 is specified over the -40°C to +85°C operating temperature range.



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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ORDERING INFORMATION ⁽¹⁾								
PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER			
ADS5295	TQFP-80	PFP	-40°C to +85°C	ADS5295	ADS5295IPFP			

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or visit the device product folder at www.ti.com.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Over operating free-air temperature range, unless otherwise noted.

PA	RAMETER	VALUE	UNIT
	AVDD	-0.3 to 2.2	V
Supply voltage range	LVDD	-0.3 to 2.2	V
	AGND and LGND	-0.3 to 0.3	V
Voltage between	AVDD to LVDD (when AVDD leads LVDD)	0 to 2.2	V
	LVDD to AVDD (when LVDD leads AVDD)	0 to 2.2	V
	INP, INN	-0.3 to min (2.2, AVDD + 0.3)	V
Voltage applied to	RESET, SCLK, SDATA, \overline{CS} , PD, SYNC, CLKP, CLKN ⁽²⁾	-0.3 to min (2.2, AVDD + 0.3)	V
	Digital outputs	-0.3 to min (2.2, LVDD + 0.3)	V
	Operating free-air, T _A	-40 to +85	°C
Temperature range	Operating junction, T _J	+105	°C
	AVALULVALULAVDD $-0.3 \text{ to } 2.2$ LVDD $-0.3 \text{ to } 2.2$ AGND and LGND $-0.3 \text{ to } 0.3$ AVDD to LVDD (when AVDD leads LVDD)0 to 2.2LVDD to AVDD (when LVDD leads AVDD)0 to 2.2LVDD to AVDD (when LVDD leads AVDD)0 to 2.2INP, INN $-0.3 \text{ to min } (2.2, AVDD + 0.3)$ RESET, SCLK, SDATA, \overline{CS} , PD, SYNC, CLKP, CLKN ⁽²⁾ $-0.3 \text{ to min } (2.2, AVDD + 0.3)$ Digital outputs $-0.3 \text{ to min } (2.2, LVDD + 0.3)$ Operating free-air, T_A $-40 \text{ to } +85$ Operating junction, T_J $+105$ Storage, T_{stg} $-55 \text{ to } +150$ Human body model (HBM)2000	°C	
Electrostatic discharge (ESD) rating	Human body model (HBM)	2000	V

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

(2) When AVDD is turned off, TI recommends switching off the input clock (or ensuring the voltage on CLKP and CLKN is less than |0.3 V|. This setting prevents the ESD protection diodes at the clock input pins from turning on.

THERMAL INFORMATION

		ADS5295	
	THERMAL METRIC ⁽¹⁾	PFP (TQFP)	UNITS
		80 PINS	
θ_{JA}	Junction-to-ambient thermal resistance	30.8	
θ _{JCtop}	Junction-to-case (top) thermal resistance	6.3	
θ_{JB}	Junction-to-board thermal resistance	8.3	8CAM
ΨJT	Junction-to-top characterization parameter	0.2	°C/vv
Ψ_{JB}	Junction-to-board characterization parameter	8.2	
θ _{JCbot}	Junction-to-case (bottom) thermal resistance	0.3	

(1) For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report, SPRA953.



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RECOMMENDED OPERATING CONDITIONS

			MIN	NOM	MAX	UNIT
SUPPLIES						
AVDD	Analog supply voltage		1.7	1.8	1.9	V
LVDD	Digital supply voltage		1.7	1.8	1.9	V
ANALOG INP	PUTS					
V _{ID}	Differential input voltage range			2		V _{PP}
	Input common-mode voltage		VC	VCM ± 0.05		
REFT	External reference mode			1.45		V
REFB	External reference mode			0.45		V
VCM	Common-mode voltage output			0.95		V
CLOCK INPU	ITS (ADCLK Input Sample Rate)					
		One-wire LVDS interface	10		80	MSPS
	ADCLK input sample rate $(1 / t_C)$	Two-wire LVDS interface	10		100	MSPS
		Sine-wave, ac-coupled		NOM MAX 1.8 1.9 1.8 1.9 2 3 $3M \pm 0.05$ 1.45 0.45 0.95 0.95 0.95 1.6 0.7 < 0.3		V _{PP}
	Input clock amplitude differential	LVPECL, ac-coupled		1.6		V _{PP}
		LVDS, ac-coupled		0.7		V _{PP}
	Input clock CMOS single-ended	V _{IL}		< 0.3		V
	(VCLKP)	V _{IH}		> 1.5		V
	Input clock duty cycle		35	50	65	%
DIGITAL OUT	IPUTS					
	ADCLKP and ADCLKN outputs (L	VDS), one-wire	(sampl	1x e rate in MSPS)		MHz
	ADCLKP and ADCLKN outputs (L	VDS), two-wire	(sampl	0.5x e rate in MSPS)		MHz
	LCLKP and LCLKN outputs	12x serialization	(sampl	6x e rate in MSPS)	2 1.45 0.45 0.95 	MHz
	(LVDS), one-wire	10x serialization	(sampl	.7 1.8 1.9 .7 1.8 1.9 .7 1.8 1.9 2 VCM \pm 0.05 1.45 0.45 0.95 10 80 10 100 1.5 1.6 0.7 < 0.3		MHz
	LCLKP and LCLKN outputs	12x serialization	(sampl	3x (sample rate in MSPS)		MHz
	(LVDS), two-wire	10x serialization	(sampl	2.5x e rate in MSPS)		MHz



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ELECTRICAL CHARACTERISTICS: General

Typical values are at $T_A = +25^{\circ}$ C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.

Minimum and maximum values are across the full temperature range of $T_{MIN} = -40$ °C to $T_{MAX} = +85$ °C, AVDD = 1.8 V, and LVDD = 1.8 V.

	PARA	METER	TEST CONDITIONS	MIN TYP	MAX	UNIT
RESOLU	TION					
	Resolution				12	Bits
ANALOG	INPUTS					
	Differential input	voltage range		2.0		V _{PP}
	Differential input	resistance	At dc	2		kΩ
	Differential input	capacitance	At dc	3.7		pF
	Analog input bar	ndwidth		500		MHz
	Analog input cor (per input pin)	nmon-mode current		1		µA/MSPS
VCM	Common-mode	output voltage		0.95		V
	VCM output curr	ent capability		5		mA
DYNAMI	C ACCURACY					
Eo	Offset error			-20	20	mV
E _{GREF}	Gain error	Resulting from internal reference inaccuracy alone		-1.5	1.5	%FS
E _{GCHAN}		Of channel itself		0.5		%FS
	E _{GCHAN} tempera	ture coefficient		< 0.01		∆%FS/°C
POWER	SUPPLY					
IAVDD	Analog supply c	urrent	100 MSPS	206	225	mA
ILVDD	Output buffer su	pply current	100 MSPS, two-wire LVDS interface, 350-mV swing with $100-\Omega$ external termination	150	163	mA
AVDD	Analog power		100 MSPS	370.8		mW
LVDD	Digital power		100 MSPS, two-wire LVDS interface, 350-mV swing with 100- Ω external termination	270		mW
	Total power		100 MSPS, two-wire LVDS interface, 350-mV swing with 100- Ω external termination	640.8		mW
	Global power-do	wn			45	mW
	Standby power			192		mW



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ELECTRICAL CHARACTERISTICS: Dynamic Performance

Typical values are at $T_A = +25^{\circ}$ C, AVDD = 1.8 V, LVDD = 1.8 V, maximum rated sampling frequency, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.

Minimum and maximum values are across the full temperature range of $T_{MIN} = -40$ °C to $T_{MAX} = +85$ °C, AVDD = 1.8 V, and LVDD = 1.8 V.

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
		f _{IN} = 5 MHz	67.5	70.6		dBFS
SNR	Signal-to-noise ratio	f _{IN} = 30 MHz		70.4		dBFS
		f _{IN} = 70 MHz		69.7		dBFS
		f _{IN} = 5 MHz	66	70.4		dBFS
SINAD	Signal-to-noise and distortion ratio	f _{IN} = 30 MHz		70		dBFS
		f _{IN} = 70 MHz		68.9	0.82 1.1	dBFS
		f _{IN} = 5 MHz	72.5	86		dBc
SFDR	Spurious-free dynamic range	f _{IN} = 30 MHz		79		dBc
		f _{IN} = 70 MHz		76.3		dBc
		f _{IN} = 5 MHz	71	85		dBc
THD	Total harmonic distortion	f _{IN} = 30 MHz		78.4		dBc
		f _{IN} = 70 MHz		75.8		dBc
		f _{IN} = 5 MHz	72.5	89.5		dBc
HD2	Second-harmonic distortion	f _{IN} = 30 MHz		89.5		dBc
		f _{IN} = 70 MHz		89.5	D.6 D.4 D.4 D.4 D.4 D.4 D.4 TO D.4 70 D.4 70 D.4 70 D.4 70 D.4 70 D.5 D.6.4 D.5 D.6 D.7 D.8 D.9 D.9 D.9 D.9 D.9 D.9 D.9 D.9 </td <td>dBc</td>	dBc
		f _{IN} = 5 MHz	72.5	86		dBc
HD3	Third-harmonic distortion	f _{IN} = 30 MHz		79		dBc
		f _{IN} = 70 MHz		76.4		dBc
		f _{IN} = 5 MHz	75	95		dBc
	Worst spur (other than second and third harmonics)	f _{IN} = 30 MHz		93		dBc
		f _{IN} = 70 MHz		82.3		dBc
IMD	Two-tone intermodulation distortion	$f_1 = 8 \text{ MHz}, f_2 = 10 \text{ MHz},$ each tone at -7 dBFS		86		dBc
	Crosstalk	10-MHz full-scale signal on aggressor channel; 5-MHz input signal applied on victim channel		86		dB
	Input overload recovery	Recovery to within 1% (of full-scale) for 6-dB overload with sine-wave input		1		Clock cycle
PSRR	AC power-supply rejection ratio	For 50-mV $_{\text{PP}}$ signal on AVDD supply, up to 10 MHz, no signal applied to analog inputs		60		dB
ENOB	Effective number of bits	f _{IN} = 5 MHz		11.4		LSBs
DNL	Differential nonlinearity	f _{IN} = 5 MHz	-0.82	±0.05	0.82	LSBs
INL	Integrated nonlinearity	f _{IN} = 5 MHz		0.4	1.1	LSBs



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DIGITAL CHARACTERISTICS

The dc specifications refer to the condition where the digital outputs are not switching, but are permanently at a valid logic level '0' or '1'. AVDD = 1.8 V and DRVDD = 1.8 V.

	PARAMET	ER	TEST CONDITIONS	MIN	TYP M	IAX	UNIT
DIGITA	L INPUTS (RESET, SCLK, S	DATA, CS, SYNC, PDN)		·			
V _{IH}	High-level input voltage		All pins support 1.8-V and 3.3-V CMOS logic levels	1.3			V
V _{IL}	Low-level input voltage		All pins support 1.8-V and 3.3-V CMOS logic levels			0.4	V
IIH	High-level input current	CS, SDATA, SCLK ⁽¹⁾	V _{HIGH} = 1.8 V		6		μA
I _{IL}	Low-level input current	CS, SDATA, SCLK ⁽¹⁾	V _{LOW} = 0 V		0.1		μA
DIGITA	L OUTPUTS (CMOS INTERI	FACE: SDOUT)					
V _{OH}	High-level output voltage			AVDD - 0.1			V
V _{OL}	Low-level output voltage					0.1	V
DIGITA	L OUTPUTS (LVDS INTERF	ACE: OUT1A_P, OUT1A_I	N to OUT8A_P, OUT8A_N and OUT1B_P, OU	T1B_N to OUT8B_P	, OUT8B_N)		
V _{ODH}	/ _{ODH} High-level output differential voltage ⁽²⁾ 300 485				485	mV	
V _{ODL}	Low-level output differentia	l voltage ⁽²⁾		-485	-	300	mV
V _{OCM}	Output common-mode volta	age		0.95		1.35	V

 $\overline{\text{CS}},$ SDATA, and SCLK have an internal 220-k Ω pull-down resistor. With an external 100- Ω termination. (1)

(2)



TIMING REQUIREMENTS⁽¹⁾

Typical values are at +25°C, AVDD = 1.8 V, LVDD = 1.8 V, sampling frequency = 100 MSPS, sine-wave input clock, C_{LOAD} = 5 pF, and R_{LOAD} = 100 Ω , unless otherwise noted.

Minimum and maximum values are across the full temperature range of $T_{MIN} = -40$ °C to $T_{MAX} = +85$ °C, AVDD = 1.8 V, and LVDD = 1.7 V to 1.9 V.

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _A	Aperture delay			4		ns
	Aperture delay matching	Between any two channels of the same device		±200		ps
	Variation of aperture delay	Between two devices at the same temperature and LVDD supply		±1		ns
tj	Aperture jitter	Sample uncertainty		320		fs rms
		Time to valid data after coming out of standby		5		μs
	Wake-up time	Time to valid data after coming out of global power- down mode		100		μs
	ADC latera (2)	One-wire LVDS Output interface		12		Clock cycles
	ADC latency	Two-wire LVDS Output interface		16		Clock cycles
TWO-WI	RE, 12x SERIALIZATION					
t _{SU}	Data setup time	Data valid to zero-crossing of LCLKP	0.52			ns
t _H	Data hold time	Zero-crossing of LCLKP to data becoming invalid	0.62			ns
t _{PDI}	Clock propagation delay	Input clock rising edge crossover to output clock rising edge crossover		$t_{PDI} = (11/12) \\ \times t_{S} + \\ t_{DELAY}$		ns
t _{DELAY}	Delay time		8.5	11	13.5	ns
	LVDS bit clock duty cycle	Duty cycle of differential clock (LCLKP – LCLKN)		50		%
ACROSS	ALL SERIALIZATION MODES					
t _{FALL}	Data fall time	Rise time measured from −100 mV to +100 mV, 10 MSPS ≤ sampling frequency ≤ 100 MSPS		0.11		ns
t _{RISE}	Data rise time	Rise time measured from –100 mV to +100 mV, 10 MSPS ≤ sampling frequency ≤ 100 MSPS		0.11		ns
t _{CLKRISE}	Output clock rise time	Rise time measured from −100 mV to +100 mV, 10 MSPS ≤ sampling frequency ≤ 100 MSPS		0.11		ns
t _{CLKFALL}	Output clock fall time	Rise time measured from –100 mV to +100 mV, 10 MSPS ≤ sampling frequency ≤ 100 MSPS		0.11		ns

(1) Timing parameters are ensured by design and characterization, but are not tested in production.

(2) At higher frequencies, tPDI is greater than one clock period and the overall latency = ADC latency + 1.

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TEXAS INSTRUMENTS

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Table 1. Two-Wire, 12x Serialization⁽¹⁾⁽²⁾

SAMPLING	SETUP TIME (ns)			HOLD TIME (ns)			t _{PDI} = (11/12) × t _S + t _{DELAY} Where t _{DELAY} is specified as below, ns		
FREQUENCY (MSPS)	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX
10	7.80			8.00			8.5	11	13.5
30	2.40			2.50			8.5	11	13.5
50	1.10			1.60			8.5	11	13.5
65	0.83			1.25			8.5	11	13.5
80	0.60			1.00			8.5	11	13.5
100	0.52			0.62			8.5	11	13.5

(1) All the timing specifications are taken with default output clock and data delay settings (0 ps).

(2) Refer to the *Programmable LVDS Output Clock and Data Edges* section in the Application Information for output clock and data delay options.

Table 2. One-Wire, 12x Serialization⁽¹⁾⁽²⁾

SAMPLING	SETUP TIME (ns)			HOLD TIME (ns)			t _{PDI} = (9/12) × t _S + t _{DELAY} Where t _{DELAY} is specified as below, ns		
FREQUENCY (MSPS)	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX
10	3.90			4.00			8	10	12
30	1.00			1.30			8	10	12
50	0.60			0.57			8	10	12
65	0.40			0.34			8	10	12
80	0.22			0.24			8	10	12

(1) All the timing specifications are taken with default output clock and data delay settings (0 ps).

(2) Refer to the *Programmable LVDS Output Clock and Data Edges* section in the Application Information for output clock and data delay options.

Table 3. Two-Wire, 10x Serialization⁽¹⁾⁽²⁾

SAMPLING FREQUENCY	SET	UP TIME (ns)		HOLD TIME (ns)			
(MSPS)	MIN	TYP	MAX	MIN	ТҮР	MAX	
65	1.00			1.50			
80	0.74			1.20			
100	0.44			1.00			

(1) All the timing specifications are taken with default output clock and data delay settings (0 ps).

(2) Refer to the Programmable LVDS Output Clock and Data Edges section in the Application Information for output clock and data delay options.

Table 4. One-Wire, 10x Serialization⁽¹⁾⁽²⁾

SAMPLING FREQUENCY	SETU	JP TIME (ns)		HOLD TIME (ns)			
(MSPS)	MIN	TYP	MAX	MIN	ТҮР	MAX	
65	0.51			0.60			
80	0.33			0.36			
100	0.17			0.31			

(1) All the timing specifications are taken with default output clock and data delay settings (0 ps).

(2) Refer to the *Programmable LVDS Output Clock and Data Edges* section in the Application Information for output clock and data delay options.



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PARAMETRIC MEASUREMENT INFORMATION

LATENCY TIMING

Figure 1 shows a timing diagram of the LVDS output voltage levels.







Figure 2. Latency Timing Diagram

LVDS OUTPUT TIMING

Figure 3 shows the output timing described in the Timing Requirements table.

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PARAMETRIC MEASUREMENT INFORMATION (continued)

(1) n = 0 to 11.

Figure 3. LVDS Output Timing

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PIN DESCRIPTIONS											
NAME	NO.	FUNCTION ⁽¹⁾	DESCRIPTION								
ADCLKN	30	DO	Differential LVDS frame clock (1x), negative								
ADCLKP	29	DO	Differential LVDS frame clock (1x), positive								
AGND	3, 6, 55, 58, 61, 80	G	Analog ground pin								
AVDD	9, 52, 66, 71, 74	S	Analog supply pin, 1.8 V								
CLKN	73	AI	Differential clock input, negative For a single-ended clock, tie CLKN to 0 V								
CLKP	72	AI	Differential clock input, positive								
CS	75	DI	Serial enable chip select; active low digital input								
IN1N	79	AI	Differential analog input for channel 1, negative								
IN1P	78	AI	Differential analog input for channel 1, positive								
IN2N	2	AI	Differential analog input for channel 2, negative								
IN2P	1	AI	Differential analog input for channel 2, positive								
IN3N	5	AI	Differential analog input for channel 3, negative								
IN3P	4	AI	Differential analog input for channel 3, positive								
IN4N	8	AI	Differential analog input for channel 4, negative								
IN4P	7	AI	Differential analog input for channel 4, positive								
IN5N	54	AI	Differential analog input for channel 5, negative								
IN5P	53	AI	Differential analog input for channel 5, positive								
IN6N	57	AI	Differential analog input for channel 6, negative								
IN6P	56	AI	Differential analog input for channel 6, positive								
IN7N	60	AI	Differential analog input for channel 7, negative								
IN7P	59	AI	Differential analog input for channel 7, positive								
IN8N	63	AI	Differential analog input for channel 8, negative								
IN8P	62	AI	Differential analog input for channel 8, positive								
LCLKN	32	DO	LVDS differential bit clock output pins (6x), negative								
LCLKP	31	DO	LVDS differential bit clock output pins (6x), positive								
LGND	12, 50	G	Digital ground pin								
LVDD	11, 49	S	Digital and I/O power supply, 1.8 V								
NC	67	—	Do not connect								
OUT1A_N	14	DO	Channel 1 differential LVDS negative data output, one-wire								
OUT1A_P	13	DO	Channel 1 differential LVDS positive data output, one-wire								
OUT1B_N	16	DO	Channel 1 differential LVDS negative data output, two-wire								
OUT1B_P	15	DO	Channel 1 differential LVDS positive data output, two-wire								
OUT2A_N	18	DO	Channel 2 differential LVDS negative data output, one-wire								
OUT2A_P	17	DO	Channel 2 differential LVDS positive data output, one-wire								
OUT2B_N	20	DO	Channel 2 differential LVDS negative data output, two-wire								
OUT2B_P	19	DO	Channel 2 differential LVDS positive data output, two-wire								
OUT3A_N	22	DO	Channel 3 differential LVDS negative data output, one-wire								
OUT3A_P	21	DO	Channel 3 differential LVDS positive data output, one-wire								
OUT3B_N	24	DO	Channel 3 differential LVDS negative data output, two-wire								
OUT3B_P	23	DO	Channel 3 differential LVDS positive data output, two-wire								
OUT4A_N	26	DO	Channel 4 differential LVDS negative data output, one-wire								
OUT4A_P	25	DO	Channel 4 differential LVDS positive data output, one-wire								
OUT4B_N	28	DO	Channel 4 differential LVDS negative data output, two-wire								
OUT4B_P	27	DO	Channel 4 differential LVDS positive data output, two-wire								

(1) Pin functionality: AI = analog input; DI = digital input; DO = digital output; G = ground; and S = supply.

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PIN DESCRIPTIONS (continued)										
NAME	NO.	FUNCTION ⁽¹⁾	DESCRIPTION							
OUT5B_N	34	DO	Channel 5 differential LVDS negative data output, two-wire							
OUT5B_P	33	DO	Channel 5 differential LVDS positive data output, two-wire							
OUT5A_N	36	DO	Channel 5 differential LVDS negative data output, one-wire							
OUT5A_P	35	DO	Channel 5 differential LVDS positive data output, one-wire							
OUT6B_N	38	DO	Channel 6 differential LVDS negative data output, two-wire							
OUT6B_P	37	DO	Channel 6 differential LVDS positive data output, two-wire							
OUT6A_N	40	DO	Channel 6 differential LVDS negative data output, one-wire							
OUT6A_P	39	DO	Channel 6 differential LVDS positive data output, one-wire							
OUT7B_N	42	DO	Channel 7 differential LVDS negative data output, two-wire							
OUT7B_P	41	DO	Channel 7 differential LVDS positive data output, two-wire							
OUT7A_N	44	DO	Channel 7 differential LVDS negative data output, one-wire							
OUT7A_P	43	DO	Channel 7 differential LVDS positive data output, one-wire							
OUT8B_N	46	DO	Channel 8 differential LVDS negative data output, two-wire							
OUT8B_P	45	DO	Channel 8 differential LVDS positive data output, two-wire							
OUT8A_N	48	DO	Channel 8 differential LVDS negative data output, one-wire							
OUT8A_P	47	DO	Channel 8 differential LVDS positive data output, one-wire							
PD	10	DI	Power-down control input pin							
REFB	69	AI	Negative reference input/output							
REFT	70	AI	Positive reference input/output							
RESET	51	DI	Active high RESET input							
SCLK	77	DI	Serial clock input							
SDATA	76	DI	Serial data input							
SDOUT	64	DO	Serial data output							
SYNC	65	DI	Synchronization input for reduced output data rate							
VCM	68	AI	Common-mode output pin, 0.95-V output							



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TYPICAL CHARACTERISTICS: General

Typical values are at T_A = +25°C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.

> Figure 7. FFT FOR 5-MHz INPUT SIGNAL (Sample Rate = 50 MSPS)

(Sample Rate = 100 MSPS)

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TYPICAL CHARACTERISTICS: General (continued)

Typical values are at $T_A = +25$ °C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.





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TYPICAL CHARACTERISTICS: General (continued)

Typical values are at $T_A = +25^{\circ}$ C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.



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TYPICAL CHARACTERISTICS: General (continued)

Typical values are at $T_A = +25^{\circ}$ C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.



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TYPICAL CHARACTERISTICS: General (continued)

Typical values are at $T_A = +25^{\circ}$ C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.



 Adjacent channel: Neighboring channels on the immediate left and right of the channel of interest. Near channel: Channels on the same side of the package, except the immediate neighbors. Far channel: Channels on the opposite side of the package.

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TYPICAL CHARACTERISTICS: Digital Processing

Typical values are at $T_A = +25^{\circ}$ C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.





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TYPICAL CHARACTERISTICS: Digital Processing (continued)

Typical values are at $T_A = +25^{\circ}$ C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.



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TYPICAL CHARACTERISTICS: Digital Processing (continued)

Typical values are at $T_A = +25$ °C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.





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TYPICAL CHARACTERISTICS: Power Consumption

Typical values are at $T_A = +25^{\circ}$ C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.



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TYPICAL CHARACTERISTICS: Power Consumption (continued)

Typical values are at $T_A = +25^{\circ}$ C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.



Figure 40. TOTAL POWER PER CHANNEL



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TYPICAL CHARACTERISTICS: Contour

Typical values are at $T_A = +25^{\circ}$ C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.



Figure 41. SIGNAL-TO-NOISE RATIO vs INPUT AND SAMPLING FREQUENCIES



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TYPICAL CHARACTERISTICS: Contour (continued)

Typical values are at $T_A = +25^{\circ}$ C, AVDD = 1.8 V, LVDD = 1.8 V, 50% clock duty cycle, 100 MSPS, two-wire LVDS interface, and -1-dBFS differential analog input, unless otherwise noted.



Figure 42. SPURIOUS-FREE DYNAMIC RANGE vs INPUT AND SAMPLING FREQUENCIES



DEVICE CONFIGURATION

SERIAL INTERFACE

The ADC has a set of internal registers that can be accessed by the serial interface formed by the \overline{CS} (serial interface enable), SCLK (serial interface clock), and SDATA (serial interface data) pins. Serially shifting bits into the device is enabled when \overline{CS} is low. The serial data (on the SDATA pin) are latched at every SCLK falling edge when \overline{CS} is active (low). The serial data are loaded into the register at every 24th SCLK rising edge when \overline{CS} is low. When the word length exceeds a multiple of 24 bits, the excess bits are ignored. Data can be loaded in multiples of 24-bit words within a single active \overline{CS} pulse. The first eight bits form the register address and the remaining 16 bits are the register data. The interface can function with SCLK frequencies from 15 MHz down to very low speeds (of a few hertz) and also with a non-50% SCLK duty cycle.

Register Initialization

After power-up, the internal registers must be initialized to default values. This initialization can be accomplished in one of two ways:

- 1. Either through a hardware reset by applying a high pulse on the RESET pin (of widths greater than 10 ns), as shown in Figure 43; or
- 2. By applying a software reset. When using the serial interface, set the RESET bit (register 00h, bit D7) high. This setting initializes the internal registers to default values and then self-resets the RESET bit low. In this case, the RESET pin is kept low (inactive).



Figure 43. Serial Interface Timing Diagram

	PARAMETER	MIN	TYP	MAX	UNIT
f _{SCLK}	SCLK frequency (equal to 1 / t _{SCLK})	>dc		15	MHz
t _{SLOADS}	CS to SCLK setup time	33			ns
t _{SLOADH}	SCLK to \overline{CS} hold time	33			ns
t _{DSU}	SDATA setup time	33			ns
t _{DH}	SDATA hold time	33			ns

Table 5. Timing Characteristics for Figure 43⁽¹⁾

(1) Typical values are at $T_A = +25^{\circ}$ C, minimum and maximum values are across the full temperature range of $T_{MIN} = -40^{\circ}$ C to $T_{MAX} = +85^{\circ}$ C, unless otherwise noted.

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Reset Timing

Figure 44 shows a timing diagram for the reset function.



Figure 44. Reset Timing Diagram

Table 6. Timing Characteristics for Figure 44.	or Figure 44 ⁽¹⁾⁽²⁾	or Fig	for	Characteristics	Timina	able 6.
------------------------------------------------	--------------------------------	--------	-----	-----------------	--------	---------

PARAMETER		TEST CONDITIONS	MIN	ТҮР	MAX	UNIT
t ₁	Power-on delay	Delay from AVDD and LVDD power-up to active RESET pulse	1			ms
t ₂	Reset pulse width	Pulse width of active RESET signal	50			ns
t ₃	Register write delay	Delay from RESET disable to \overline{CS} active		100		ns

(1) Typical values are at $T_A = +25^{\circ}$ C, minimum and maximum values are across the full temperature range of $T_{MIN} = -40^{\circ}$ C to $T_{MAX} = +85^{\circ}$ C, unless otherwise noted.

(2) A high pulse on the RESET pin is required when initialization is done via a hardware reset.



Serial Register Readout

The device includes a mode where the contents of the internal registers can be read back on the SDOUT pin. This readback mode may be useful as a diagnostic check to verify the serial interface communication between the external controller and the ADC.

By default, the SDOUT pin is in 3-state after a device power-up or reset. When the readout mode is enabled using the READOUT register bit, SDOUT serially outputs the contents of the selected register. The following steps describe how to achieve this functionality:

- 1. Set the READOUT register bit to '1'. This setting puts the device in serial readout mode. This mode prevents any further writes to the internal registers, *except* for at register 01h. Note that the READOUT bit is also located in register 01h. The device can exit readout mode by setting the READOUT bit to '0'. Note that only the contents of register 01h are unable to be read in register readout mode.
- 2. Initiate a serial interface cycle specifying the address of the register (A[7:0]) whose content must be read.
- 3. The device serially outputs the contents (D[15:0]) of the selected register on the SDOUT pin.
- 4. The external controller can latch the contents at the SCLK rising edge.

To exit serial readout mode, reset the READOUT register bit to '0', which enables writes to all device registers. At this point, the SDOUT pin is in 3-state. A detailed timing diagram for the serial readout mode is shown in Figure 45.



b) Read contents of register 0Fh. This register is initialized with 0200 (the device was previously put in global power-down).

Figure 45. Serial Readout Timing Diagram

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SERIAL INTERFACE REGISTERS MAP

 Table 7 lists the ADS5295 registers.

REGISTER																
(Hex)	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
00	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	RST
01	0	0	0	0	0	0	0	0	0	0	0	EN_HIGH_ ADDRS	0	0	0	EN_ READOUT
0A		RAMP_PAT_RESET_VAL														
0F	0	0	0	0	0	PDN_PIN_ CFG	PDN_ COMPLETE	PDN_ PARTIAL				PDN_	CH[8:1]	H[8:1]		
14	0	0	0	0	0	0	0	0				LFNS_	CH[8:1]			
1C	0	EN_FRAME _PAT	0	0		ADCLKOUT[11:0]										
23								PRBS_SI	EED[15:0]							
24			P	RBS_SEED[22:	:16]			0				INVERT	_CH[8:1]			
25	TP_HARD_ SYNC	PRBS_ SEED_ FROM_REG	PRBS_ MODE_2	PRBS_ TP_EN	0	0	0	TP_SOFT_ SYNC	0		TEST_PATT[2	:0]	BITS_CUS	TOM2[11:10]	BITS_CUSTOM1[11:10]	
26					BITS_CU	STOM1[9:0]	4	l.	l.		0	0	0	0	0	0
27					BITS_CU	STOM2[9:0]					0	0	0	0	0	0
28	EN_WORD _BIT_WISE	0	0	0	0	0	0	EN_BIT _WISE	EN_WORDWIS				SE_BY_CH[7:0)]		
29	0	0	0	0	0	0	0	0	0 0 0 0			0	0	EN_DIG_ FILTER	EN_ CHANNEL_ AVG	
2A		GAIN_C	CH4[3:0]			GAIN_	CH3[3:0]			GAIN_	CH2[3:0]			GAIN_0	CH1[3:0]	
2B		GAIN_C	CH5[3:0]			GAIN_	CH6[3:0]		GAIN_CH7[3:0] GAIN_CH8[3:0]							
2C	0	0	0	0	0	AVG_C	OUT4[1:0]	0	AVG_C	OUT3[1:0]	0	AVG_O	UT2[1:0]	0	AVG_C	DUT1[1:0]
2D	0	0	0	0	0	AVG_C	OUT8[1:0]	0	AVG_C	DUT7[1:0]	0	AVG_O	UT6[1:0]	0	AVG_C	DUT5[1:0]
2E	0	HPF_EN_ CH1		HPF_CORN	IER_CH1[3:0]		FILT	ER_TYPE_CH	1[2:0]		DEC_RATE_C	H1	0	SEL_ODD_ TAP_CH1	0	USE_ FILTER_ CH1
2F	0	HPF_EN_ CH2		HPF_CORN	IER_CH2[3:0]		FILT	ER_TYPE_CH	2[2:0]		DEC_RATE_C	H2	0	SEL_ODD_ TAP_CH2	0	USE_ FILTER_ CH2
30	0	HPF_EN_ CH3		HPF_CORN	IER_CH3[3:0]		FILT	ER_TYPE_CH	3[2:0]		DEC_RATE_C	H3	0	SEL_ODD_ TAP_CH3	0	USE_ FILTER_ CH3
31	0	HPF_EN_ CH4	HPF_CORNER_CH4[3:0]				FILT	FILTER_TYPE_CH4[2:0]			DEC_RATE_CH4		0	SEL_ODD_ TAP_CH4	0	USE_ FILTER_ CH4
32	0	HPF_EN_ CH5		HPF_CORN	IER_CH5[3:0]		FILT	ER_TYPE_CH	5[2:0]		DEC_RATE_C	H5	0	SEL_ODD_ TAP_CH5	0	USE_ FILTER_ CH5
33	0	HPF_EN_ CH6		HPF_CORN	IER_CH6[3:0]		FILT	FILTER_TYPE_CH6[2:0] DEC_RATE_CH6			H6	0	SEL_ODD_ TAP_CH6	0	USE_ FILTER_ CH6	

Table 7. Register Map

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Table 7. Register Map (continued)

REGISTER ADDRESS (Hex)	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
34	0	HPF_EN_ CH7		HPF_CORN	ER_CH7[3:0]	R_CH7[3:0] FILTER_TYPE_CH7				DEC_RATE_CH7 0			0	SEL_ODD_ TAP_CH7	0	USE_ FILTER_ CH7
35	0	HPF_EN_ CH8		HPF_CORN	ER_CH8[3:0]	۲_CH8[3:0] FILTER_TYPE_CH			8[2:0]		DEC_RATE_CH	18	0	SEL_ODD_ TAP_CH8	0	USE_ FILTER_ CH8
38	0	0	0	0	0	0	0	0	0	0	0	0	0	0	DATA_R	ATE[1:0]
42	EN_PHASE DDR	0	0	0	0	0	0	0	0	PHASE_ DDR1	PHASE_ DDR0	0	0	0	0	0
45	0	0	0	0	0	0	0	0	0	0	0	0	0	0	PAT_DESKE	W_SYNC[1:0]
46	ENABLE 46	0	FALL_SDR	0		BIT_SER_SEL			0	0	0	EN_SDR	EN_MSB_ FIRST	BTC_MODE	0	EN_2WIRE
50	ENABLE 50	0	0	0		MAP_Ch123	4_to_OUT2A			MAP_Ch12	34_to_OUT1B			MAP_Ch123	4_to_OUT1A	
51	ENABLE 51	0	0	0		MAP_Ch123	4_to_OUT3B			MAP_Ch12	34_to_OUT3A			MAP_Ch123	4_to_OUT2B	
52	ENABLE 52	0	0	0	0	0	0	0		MAP_Ch12	34_to_OUT4B			MAP_Ch123	4_to_OUT4A	
53	ENABLE 53	0	0	0		MAP_Ch567	8_to_OUT6B			MAP_Ch56	78_to_OUT5A			MAP_Ch567	8_to_OUT5B	
54	ENABLE 54	0	0	0		MAP_Ch567	8_to_OUT7A		MAP_Ch5678_to_OUT7B				MAP_Ch5678_to_OUT6A			
55	ENABLE 55	0	0	0	0	0	0	0		MAP_Ch5678_to_OUT8A				MAP_Ch5678_to_OUT8B		
5A to 65	EN_ CUSTOM_ FILT_CH1	0	0	0					1	COEFFn_	SET_CH1 ⁽¹⁾					
66 to 71	EN_ CUSTOM_ FILT_CH2	0	0	0						COEFFn_	SET_CH2 ⁽¹⁾					
72 to 7D	EN_ CUSTOM_ FILT_CH3	0	0	0						COEFFn_	SET_CH3 ⁽¹⁾					
7E to 89	EN_ CUSTOM_ FILT_CH4	0	0	0						COEFFn_	SET_CH4 ⁽¹⁾					
8A to 95	EN_ CUSTOM_ FILT_CH5	0	0	0						COEFFn_	SET_CH5 ⁽¹⁾					
96 to A1	EN_ CUSTOM_ FILT_CH6	0	0	0						COEFFn_	SET_CH6 ⁽¹⁾					
A2 to AD	EN_ CUSTOM_ FILT_CH7	0	0	0	COEFF <i>n</i> _SET_CH7 ⁽¹⁾											
AE to B9	EN_ CUSTOM_ FILT_CH8	0	0	0	COEFF <i>n_</i> SET_CH8 ⁽¹⁾											
BE	EN_LVDS _PROG	0	0	0	0	0	DELAY_	DATA_R	I	DELAY_LCLK	_R	DELAY	_DATA_F		DELAY_LCLK_	F
F0	EN_EXT_ REF	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

(1) n = 0 to 11.

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DESCRIPTION OF SERIAL INTERFACE REGISTERS

Register 00h

D15	D14	D13	D12	D11	D10	D9	D8
0	0	0	0	0	0	0	0
D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	0	RST

Bits D[15:1] Must v

Must write '0'

Bit D0

RST

0 = Normal operation (default)

1 = Self-clearing software RESET; after reset, this bit is set to '0'

Register 01h

D15	D14	D13	D12	D11	D10	D9	D8
0	0	0	0	0	0	0	0
D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	EN_HIGH_ ADDRS	0	0	0	EN_READOUT

Bits D[15:5]	Must write '0'
Bit D4	EN_HIGH_ADDRS
	0 = Access to register F0h disabled (default) 1 = Access to register F0h enabled
Bits D[3:1]	Must write '0'
Bit D0	EN_READOUT
	0 = Normal operation (default) 1 = READOUT of registers mode using the SDOUT pin enabled
Register 0Ah	

D15	D14	D13	D12	D11	D10	D9	D8		
RAMP_PAT_RESET_VAL									
D7	D6	D5	D4	D3	D2	D1	D0		
			RAMP_PAT_	_RESET_VAL					

Bits D[15:0] RAMP_PAT_RESET_VAL

The starting value of digital ramp test pattern can be programmed using these register bits. By default, after a reset, the starting value is 0000h.



Register 0Fh

D15	D14	D13	D12	D11	D10	D9	D8		
0	0	0	0	0	PDN_PIN_CFG	PDN_ COMPLETE	PDN_PARTIAL		
D7	D6	D5	D4	D3	D2	D1	D0		
PDN CHI8:11									

All bits default to '0' after reset.

Bits D[15:11]	Must write '0'
Bit D10	PDN_PIN_CFG
	0 = PD pin configured for complete power-down mode 1 = PD pin configured for partial power-down mode
Bit D9	PDN_COMPLETE
	0 = Normal operation 1 = Register mode for complete power-down; slow recovery from power-down
Bit D8	PDN_PARTIAL
	0 = Normal operation 1 = Partial power-down mode; fast recovery from power-down
Bits D[7:0]	PDN_CH[8:1]
	0 = Normal operation 1 = Individual channel ADC power-down mode
Register 14h	
D / F	

D15	D14	D13	D12	D11	D10	D9	D8	
0	0	0	0	0	0	0	0	
D7	D6	D5	D4	D3	D2	D1	D0	
LFNS_CH[8:1]								

Bits D[15:8] Must write '0'

Bits D[7:0] LFNS_CH[8:1]

0 = LFNS disabled (default)

1 = Low-frequency noise suppression (LFNS) mode enabled for individual channels



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Register 1Ch

D15	D14	D13	D12	D11	D10	D9	D8	
0	EN_FRAME_ PAT	0	0	ADCLKOUT[11:0]				
D7	D6	D5	D4	D3	D2	D1	D0	
ADCLKOUT[11:0]								

All bits default to '0' after reset.

Bit D15	Must write '0'
Bit D14	EN_FRAME_PAT
	0 = Normal operation on frame clock (default) 1 = Enables output frame clock to be programmed through a pattern specified by ADCCLKOUT register bits
Bits D[13:12]	Must write '0'
Bits D[11:0]	ADCLKOUT[11:0]

These bits create the 12-bit pattern for the frame clock on the ADCLKP, ADCLKN pins.

Register 23h

D15	D14	D13	D12	D11	D10	D9	D8		
PRBS_SEED[15:0]									
D7	D6	D5	D4	D3	D2	D1	D0		
PRBS_SEED[15:0]									

Bits D[15:0] PRBS_SEED[15:0]

These bits are the lower 16 bits of the PRBS pattern starting seed value. The starting seed value of the PRBS test pattern can be specified using these register bits

Register 24h

D15	D14	D13	D12	D11	D10	D9	D8
PRBS_SEED[22:16]							
D7	D6	D5	D4	D3	D2	D1	D0
INVERT_CH[8:1]							

All bits default to '0' after reset.

Bits D[15:9]	PRBS_SEED[22:16]
	These bits are the seven upper bits of the PRBS seed starting value.
Bit D8	Must write '0'
Bits D[7:0]	INVERT_CH[8:1]
	0 = Normal configuration Normally, the INP pin represents the positive analog input pin and INN represents the complementary negative input.
	1 = The polarity of the analog input pins is electrically swapped Setting the INVERT_CH[8:1] bits causes the inputs to be swapped. INN now represents the positive input and INP represents the negative input.



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All bits default to '0' after reset.

Bit D15	TP_HARD_SYNC
	0 = Inactive 1 = The external SYNC feature is enabled for syncing test patterns
Bit D14	PRBS_SEED_FROM_REG
	0 = Disabled 1 = The PRBS seed is now able to be chosen from registers 23h and 24h
Bit D13	PRBS_MODE_2
	The PRBS 9-bit LFSR (23-bit LFSR) is the default mode.
Bit D12	PRBS_TP_EN
	0 = PRBS test pattern disabled 1 = PRBS test pattern enabled
Bits D[11:9]	Must write '0'
Bit D8	TP_SOFT_SYNC
	0 = No sync 1 = Software sync bit for the test patterns on all eight channels
Bit D7	Must write '0'
Bit D6	TEST_PATT2
	0 = Normal operation 1 = A repeating full-scale ramp pattern is enabled on the outputs; ensure that bits D4 and D5 are '0'
Bit D5	TEST_PATT1
	0 = Normal operation 1 = Enables a mode where the output toggles between two defined codes; ensure that bits D4 and D6 are '0'
Bit D4	TEST_PATT0
	0 = Normal operation 1 = Enables a mode where the output is a constant specified code; ensure that bits D5 and D6 are '0'
Bits D[3:2]	BITS_CUSTOM2[11:10]
	These bits are the two MSBs for the second code of the dual custom patterns.
Bits D[1:0]	BITS_CUSTOM1[11:10]
	These bits are the two MSBs for the single custom pattern (and for the first code of the dual custom patterns).

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Register 26h

D15	D14	D13	D12	D11	D10	D9	D8		
BITS_CUSTOM1[9:0]									
D7	D6	D5	D4	D3	D2	D1	D0		
BITS_CUSTOM1[9:0]		0	0	0	0	0	0		

Bits D[15:6] BITS_CUSTOM1[9:0]

These bits are the 10 lower bits for the single custom pattern (and for the first code of the dual custom pattern).

Bits D[5:0] Must write '0'

Register 27h

D15	D14	D13	D12	D11	D10	D9	D8	
BITS_CUSTOM2[9:0]								
D7	D6	D5	D4	D3	D2	D1	D0	
BITS_CUSTOM2[9:0]		0	0	0	0	0	0	

Bits D[15:6] BITS_CUSTOM2[9:0]

These bits are the 10 lower bits for the second code of the dual custom pattern.

Bits D[5:0] Must write '0'


Register 28h

D15	D14	D13	D12	D11	D10	D9	D8
EN_WORD_ BIT_WISE	0	0	0	0	0	0	EN_BIT_WISE
D7	D6	D5	D4	D3	D2	D1	D0
			EN_WORDWIS	SE_BY_CH[7:0]			

All bits default to '0' after reset.

Bit D15	EN_WORD_BIT_WISE
	This bit enables the bit order output in two-wire mode. 0 = Byte-wise
	1 = Word-wise if D[7:0] = 1 (bit-wise if D8 = 1 and D[7:0] = 0)
Bits D[14:9]	Must write '0'
Bit D8	EN_BIT_WISE
	1 = Bit-wise if D15 =1 and D[7:0] = 0
Bits D[7:0]	EN_WORDWISE_BY_CH[7:0]
	0 = Bit-wise if D15 = 1 and D8 = 1 1 = Word-wise if D15 = 1

Register 29h

D15	D14	D13	D12	D11	D10	D9	D8
0	0	0	0	0	0	0	0
D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	EN_DIG_ FILTER	EN_CHANNEL _AVG

Bits D[15:2] Must write '0'

0 = Global control digital filter disabled(default)

1 = Global control digital filter enabled

Bit D0 EN_CHANNEL_AVG

- 0 = Channel averaging is disabled (default)
- 1 = Channel averaging is enabled and specified by the AVG_OUT*n* register bits

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Register 2Ah

D15	D14	D13	D12	D11	D10	D9	D8		
	GAIN_C	H4[3:0]			GAIN_C	H3[3:0]			
D7	D6	D5	D4	D3	D2	D1	D0		
	GAIN_C	H2[3:0]			GAIN_C	H1[3:0]			
Bits D[15:12]	GAIN_C	H4[3:0]		. for the second					
	These bi	ts set the prog	grammable ga	in for channel	4.				
Bits D[11:8]] GAIN_CH3[3:0]								
	These bits set the programmable gain for channel 3.								
Bits D[7:4]	GAIN_CH2[3:0]								
	These bi	ts set the prog	grammable ga	in for channel	2.				
Bits D[3:0]	GAIN_C	H1[3:0]							
	These bi	ts set the prog	grammable ga	in for channel	1.				

Register 2Bh

D15	D14	D13	D12	D11	D10	D9	D8	
GAIN_CH5[3:0]				GAIN_CH6[3:0]				
D7	D6	D5	D4	D3	D2	D1	D0	
GAIN_CH7[3:0]				GAIN_C	H8[3:0]			

Bits D[15:12]	GAIN_CH5[3:0]
	These bits set the programmable gain for channel 5.
Bits D[11:8]	GAIN_CH6[3:0]
	These bits set the programmable gain for channel 6.
Bits D[7:4]	GAIN_CH7[3:0]
	These bits set the programmable gain for channel 7.
Bits D[3:0]	GAIN_CH8[3:0]

These bits set the programmable gain for channel 8.



Register 2Ch

D15	D14	D13	D12	D11	D10	D9	D8
0	0	0	0	0	AVG_OL	JT4[1:0]	0
D7	D6	D5	D4	D3	D2	D1	D0
AVG_C)UT3[1:0]	0	AVG_O	UT2[1:0]	0	AVG_O	UT1[1:0]

Bits D[15:11]	Must write '0'
---------------	----------------

Bits D[10:9]	AVG_OUT4[1:0]
	These bits set the averaging control for what is transmitted on the LVDS output OUT4.
Bit D8	Must write '0'
Bits D[7:6]	AVG_OUT3[1:0]
	These bits set the averaging control for what is transmitted on the LVDS output OUT3.
Bit D5	Must write '0'
Bits D[4:3]	AVG_OUT2[1:0]
	These bits set the averaging control for what is transmitted on the LVDS output OUT2.
Bit D2	Must write '0'
Bits D[1:0]	AVG_OUT1[1:0]
	These bits set the averaging control for what is transmitted on the LVDS output OUT1.

Register 2Dh

D15	D14	D13	D12	D11	D10	D9	D8
0	0	0	0	0	AVG_O	JT8[1:0]	0
D7	D6	D5	D4	D3	D2	D1	D0
AVG_C)UT7[1:0]	0	AVG_O	UT6[1:0]	0	AVG_O	JT5[1:0]

Bits D[15:11]	Must write '0'
Bits D[10:9]	AVG_OUT8[1:0]
	These bits set the averaging control for what is transmitted on the LVDS output OUT8.
Bit D8	Must write '0'
Bits D[7:6]	AVG_OUT7[1:0]
	These bits set the averaging control for what is transmitted on the LVDS output OUT7.
Bit D5	Must write '0'
Bits D[4:3]	AVG_OUT6[1:0]
	These bits set the averaging control for what is transmitted on the LVDS output OUT6.
Bit D2	Must write '0'
Bits D[1:0]	AVG_OUT5[1:0]
	These bits set the averaging control for what is transmitted on the LVDS output OUT5.



SBAS595-DECEMBER 2012 Register 2Eh

D15	D14	D13	D12	D11	D10	D9	D8		
0	HPF_EN_CH1			FILTER_T	/PE_CH1[2:0]				
D7	D6	D5	D4	D3	D2	D1	D0		
FILTER_TYPE _CH1[2:0]	DE	EC_RATE_CH1[2	:0]	0	SEL_ODD_ TAP_CH1	0	USE_FILTER_ CH1		
Bit D15	Must wr	Must write '0'							
Bit D14	HPF_EN	_CH1							
	This bit e	enables the H	PF filter for cha	annel 1.					
Bits D[13:10]	HPF_CC	RNER _CH1	[3:0]						
	These bi	ts program th	e HPF corner t	for channel 1.					
Bits D[9:7]	FILTER_	FILTER_TYPE_CH1[2:0]							
	These bi	ts select the t	ype of filter on	channel 1.					
Bits D[6:4]	DEC_RA	TE_CH1[2:0]	l						
	These bi	ts set the dec	imation factor	for the filter on	channel 1.				
Bit D3	Must wr	ite '0'							
Bit D2	SEL_OD	D_TAP_CH1							
	This bit e	enables the o	dd tap filter for	channel 1.					
Bit D1	Must wr	ite '0'							
Bit D0	USE_FIL	TER_CH1							
	This bit e	enables the fil	ter for channel	1.					





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Register 2Fh

Bit D15	Must write '0'
Bit D14	HPF_EN_CH2
	This bit enables the HPF filter for channel 2.
Bits D[13:10]	HPF_CORNER _CH2[3:0]
	These bits program the HPF corner for channel 2.
Bits D[9:7]	FILTER_TYPE_CH2[2:0]
	These bits select the type of filter on channel 2.
Bits D[6:4]	DEC_RATE_CH2[2:0]
	These bits set the decimation factor for the filter on channel 2.
Bit D3	Must write '0'
Bit D2	SEL_ODD_TAP_CH2
	This bit enables the odd tap filter for channel 2.
Bit D1	Must write '0'
Bit D0	USE_FILTER_CH2
	This bit enables the filter for channel 2.



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D15	D14	D13	D12	D11	D10	D9	D8
0	HPF_EN_CH3		HPF_CORN	IER _CH3[3:0]	FILTER_TYPE_CH3[2:0		
D7	D6	D5	D4	D3	D2	D1	D0
FILTER_TYPE _CH3[2:0]	DI	EC_RATE_CH3[2	:0]	0	SEL_ODD_ TAP_CH3	0	USE_FILTER_ CH3
Bit D15	Must wr	rite '0'					
Bit D14	HPF_EN	N_CH3					
	This bit	enables the H	PF filter for ch	annel 3.			
Bits D[13:10]] HPF_CC	ORNER _CH3	[3:0]				
	These b	its program the	e HPF corner	for channel 3.			
Bits D[9:7]	FILTER	TYPE_CH3[2	2:0]				
	These b	its select the t	ype of filter or	n channel 3.			
Bits D[6:4]	DEC_R/	ATE_CH3[2:0]					
These bits set the decimation factor for the filter on channel 3.							
Bit D3	Must wr	rite '0'					
Bit D2	SEL_O	DD_TAP_CH3					
	This bit	enables the oc	d tap filter for	channel 3.			
Bit D1	Must wr	rite '0'					
Bit D0	USE_FII	LTER_CH3					

This bit enables the filter for channel 3.





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Register 31h

Bit D15	Must write '0'
Bit D14	HPF_EN_CH4
	This bit enables the HPF filter for channel 4.
Bits D[13:10]	HPF_CORNER _CH4[3:0]
	These bits program the HPF corner for channel 4.
Bits D[9:7]	FILTER_TYPE_CH4[2:0]
	These bits select the type of filter on channel 4.
Bits D[6:4]	DEC_RATE_CH4[2:0]
	These bits set the decimation factor for the filter on channel 4.
Bit D3	Must write '0'
Bit D2	SEL_ODD_TAP_CH4
	This bit enables the odd tap filter for channel 4.
Bit D1	Must write '0'
Bit D0	USE_FILTER_CH4
	This bit enables the filter for channel 4.



Register 32h

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D15	D14	D13	D12	D11	D10	D9	D8		
0	HPF_EN_CH5			FILTER_T	FILTER_TYPE_CH5[2:0]				
D7	D6	D6 D5 D4 D3 D2					D0		
FILTER_TYPE _CH5[2:0]	DE	EC_RATE_CH5[2	:0]	0	SEL_ODD_ TAP_CH5	0	USE_FILTER_ CH5		
Bit D15	Must wr	Must write '0'							
Bit D14	HPF_EN	I_CH5							
	This bit e	enables the HI	PF filter for cha	annel 5.					
Bits D[13:10]	HPF_CC	ORNER _CH5[[3:0]						
	These bi	These bits program the HPF corner for channel 5.							
Bits D[9:7]	FILTER_	FILTER_TYPE_CH5[2:0]							
	These bi	its select the ty	ype of filter on	channel 5.					
Bits D[6:4]	DEC_RA	ATE_CH5[2:0]							
	These bi	its set the deci	imation factor	for the filter on	channel 5.				
Bit D3	Must wr	ite '0'							
Bit D2	SEL_OD	SEL_ODD_TAP_CH5							
	This bit e	enables the oc	ld tap filter for	channel 5.					
Bit D1	Must wr	ite '0'							
Bit D0	USE_FII	LTER_CH5							
	This bit e	enables the filt	er for channel	5.					





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Register 33h

D15	D14	D13	D12	D11	D10	D9	D8
0	HPF_EN_CH6		HPF_CORNE	ER _CH6[3:0]		FILTER_T	/PE_CH6[2:0]
D7	D6	D5	D4	D3	D2	D1	D0
FILTER_TYPE _CH6[2:0]	DE	EC_RATE_CH6[2	2:0]	0	SEL_ODD_ TAP_CH6	0	USE_FILTER_ CH6

Bit D15	Must write '0'
Bit D14	HPF_EN_CH6
	This bit enables the HPF filter for channel 6.
Bits D[13:10]	HPF_CORNER _CH6[3:0]
	These bits program the HPF corner for channel 6.
Bits D[9:7]	FILTER_TYPE_CH6[2:0]
	These bits select the type of filter on channel 6.
Bits D[6:4]	DEC_RATE_CH6[2:0]
	These bits set the decimation factor for the filter on channel 6.
Bit D3	Must write '0'
Bit D2	SEL_ODD_TAP_CH6
	This bit enables the odd tap filter for channel 6.
Bit D1	Must write '0'
Bit D0	USE_FILTER_CH6
	This bit enables the filter for channel 6.



SBAS595-DECEMBER 2012 Register 34h

D15	D14	D13	D12	D11	D10	D9	D8
0	HPF_EN_CH7		HPF_CORN	IER _CH7[3:0]	FILTER_TYPE_CH7[2		
D7	D6	D5	D4	D3	D2	D1	D0
FILTER_TYPE _CH7[2:0]	DI	EC_RATE_CH7[2	:0]	0	SEL_ODD_ TAP_CH7	0	USE_FILTER_ CH7
Bit D15	Must wr	rite '0'					
Bit D14	HPF_EN	I_CH7					
	This bit e	enables the H	PF filter for ch	annel 7.			
Bits D[13:10] HPF_CORNER _CH7[3:0]							
	These b	its program th	e HPF corner	for channel 7.			
Bits D[9:7]	FILTER	_TYPE_CH7[2	2:0]				
	These b	its select the t	ype of filter or	n channel 7.			
Bits D[6:4]	DEC_R/	ATE_CH7[2:0]	l				
	These b	its set the dec	imation factor	for the filter or	n channel 7.		
Bit D3	Must wr	'ite '0'					
Bit D2	SEL_OD	DD_TAP_CH7					
	This bit e	enables the oc	d tap filter for	r channel 7.			
Bit D1	Must wr	'ite '0'					
Bit D0	USE_FII	LTER_CH7					

This bit enables the filter for channel 7.





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Register 35h

D15	D14	D13	D12	D11	D10	D9	D8
0	HPF_EN_CH8		HPF_CORNE	ER _CH8[3:0]		FILTER_T	YPE_CH8[2:0]
D7	D6	D5	D4	D3	D2	D1	D0
FILTER_TYPE CH8[2:0]	DE	C_RATE_CH8[2	2:0]	0	SEL_ODD_ TAP_CH8	0	USE_FILTER_ CH8

Bit D15Must write '0'Bit D14HPF_EN_CH8

This bit enables the HPF filter for channel 8.

Bits D[13:10] HPF_CORNER _CH8[3:0]

These bits program the HPF corner for channel 8.

Bits D[9:7] FILTER_TYPE_CH8[2:0]

These bits select the type of filter on channel 8.

Bits D[6:4] DEC_RATE_CH8[2:0]

These bits set the decimation factor for the filter on channel 8.

- Bit D3 Must write '0'
- Bit D2 SEL_ODD_TAP_CH8 This bit enables the odd tap filter for channel 8.
- Bit D1Must write '0'Bit D0USE_FILTER_CH8

This bit enables the filter for channel 8.

Register 38h

D15	D14	D13	D12	D11	D10	D9	D8
0	0	0	0	0	0	0	0
D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	DATA_R	ATE[1:0]

Bits D[15:2] Must write '0'

Bits D[1:0] DATA_RATE[1:0]

Bits D1 and D0 select the output data rate depending on the type of filter.



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Register 42h

D15	D14	D13	D12	D11	D10	D9	D8
EN_PHASE_ DDR	0	0	0	0	0	0	0
D7	D6	D5	D4	D3	D2	D1	D0
0	PHASE_DDR1	PHASE_DDR0	0	0	0	0	0
Bit D15	This bit	enables LCL	K phase prog	rammability.			
Bits D[14:7]	MUST WI						
Bits D[6:5]	PHASE	_DDR[1:0]					
	These b Refer to	its control the I the <i>Programm</i>	LCLK output p able LCLK Pl	bhase relative hase section.	to data.		
Bits D[4:0]	Must wi	rite '0'					
Register 45h							
D15	D14	D13	D12	D11	D10	D9	D8
0	0	0	0	0	0	0	0
D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	PAT_DESKE	W_SYNC[1:0]
Bits D[15:2] Bit D1	Must wi PAT_DE	rite '0' ESKEW_SYNC tive	1				
		· · ·					

1 = Sync pattern mode enabled; ensure that D0 is '0'

Bit D0 PAT_DESKEW_SYNC0

0 = Inactive

1 = Deskew pattern mode enabled; ensure that D1 is '0'

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Register 46h

D15	D14	D13	D12	D11	D10	D9	D8
ENABLE 46	0	FALL_SDR	0		BIT_SE	R_SEL	
D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	EN_SDR	EN_MSB_ FIRST	BTC_MODE	0	EN_2WIRE

All bits default to '0' after reset. Note that bit D15 must be set to '1' to enable bits D[13:0].

Bit D15	ENABLE 46
	This bit enables register 46h.
Bit D14	Must write '0'
Bit D13	FALL_SDR
	 0 = The LCLK rising or falling edge comes at the edge of the data window when operating in SDR output mode 1 = The LCLK rising or falling edge comes in the middle of the data window when operating in SDR output mode
Bit D12	Must write '0'
Bits D[11:8]	BIT_SER_SEL
	0001 = 10-bit serialization mode enabled 0010 = 12-bit serialization mode enabled 0100 = 14-bit serialization mode enabled 1000 = 16-bit serialization mode enabled Do not use any other bit combinations.
	· · · · · · · · · · · · · · · · · · ·
Bits D[7:5]	Must write '0'
Bits D[7:5] Bit D4	Must write '0' EN_SDR
Bits D[7:5] Bit D4	Must write '0' EN_SDR 0 = DDR bit clock 1 = SDR bit clock
Bits D[7:5] Bit D4 Bit D3	Must write '0' EN_SDR 0 = DDR bit clock 1 = SDR bit clock EN_MSB_FIRST
Bits D[7:5] Bit D4 Bit D3	Must write '0' EN_SDR 0 = DDR bit clock 1 = SDR bit clock EN_MSB_FIRST 0 = LSB first 1 = MSB first
Bits D[7:5] Bit D4 Bit D3 Bit D2	Must write '0' EN_SDR 0 = DDR bit clock 1 = SDR bit clock EN_MSB_FIRST 0 = LSB first 1 = MSB first BTC_MODE
Bits D[7:5] Bit D4 Bit D3 Bit D2	Must write '0' EN_SDR 0 = DDR bit clock 1 = SDR bit clock EN_MSB_FIRST 0 = LSB first 1 = MSB first BTC_MODE 0 = Binary offset (ADC data output format) 1 = Twos complement (ADC data output format)
Bits D[7:5] Bit D4 Bit D3 Bit D2 Bit D1	Must write '0' EN_SDR 0 = DDR bit clock 1 = SDR bit clock EN_MSB_FIRST 0 = LSB first 1 = MSB first BTC_MODE 0 = Binary offset (ADC data output format) 1 = Twos complement (ADC data output format) Must write '0'
Bits D[7:5] Bit D4 Bit D3 Bit D2 Bit D1 Bit D0	Must write '0' EN_SDR 0 = DDR bit clock 1 = SDR bit clock EN_MSB_FIRST 0 = LSB first 1 = MSB first BTC_MODE 0 = Binary offset (ADC data output format) 1 = Twos complement (ADC data output format) Must write '0' EN_2WIRE

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Programmable LVDS Mapping Mode Registers

Register 50h

D15	D14	D13	D12	D11	D10	D9	D8				
ENABLE 50	0	0	0		MAP_Ch1234	1_to_OUT2A					
D7	D6	D5	D4	D3	D2	D1	D0				
	MAP_Ch1234	4_to_OUT1B			MAP_Ch1234	1_to_OUT1A					
Bit D15	ENABLE	50									
	This bit e	enables bits D	[11:0] of regist	er 50h.							
Bits D[14:12]	Must wr	Must write '0'									
Bits D[11:8]	MAP_Ch	1234_to_OU	T2A								
	These bi	ts set the OU	Γ2A pin pair to	the channel of	data mapping s	election.					
Bits D[7:4]	MAP_Ch	1234_to_OU	T1B								
	These bi	ts set the OU	Г1В pin pair to	the channel of	data mapping s	election.					
Bits D[3:0]	MAP_Ch	1234_to_OU	T1A								
	These bi	ts set the OU	Г1А pin pair to	the channel of	data mapping s	election.					
Register 51h											
D15	D14	D13	D12	D11	D10	D9	D8				
ENABLE 51	0	0	0		MAP_Ch1234	1_to_OUT3B					
D7	D6	D5	D4	D3	D2	D1	D0				
	MAP_Ch1234	4_to_OUT3A			MAP_Ch1234	I_to_OUT2B					
Bit D15	ENABLE	51									
	This bit e	enables bits D	[11:0] of regist	er 51h.							
Bits D[14:12]	Must wr	ite '0'									
Bits D[11:8]	MAP_Ch	1234_to_OU	T3B								
	These bi	ts set the OUT	ГЗВ pin pair to	the channel of	data mapping s	election.					
Bits D[7:4]	MAP_Ch	1234_to_OU	T3A								
	These bi	ts set the OUT	ГЗА pin pair to	the channel of	data mapping s	election.					
Bits D[3:0]	MAP_Ch	1234_to_OU	T2B								
	These bi	ts set the OU	Γ2B pin pair to	the channel of	data mapping s	election.					



Register 52h

D15	D14	D13	D12	D11	D10	D9	D8
ENABLE 52	0	0	0	0	0	0	0
D7	D6	D5	D4	D3	D2	D1	D0
	MAP Ch123	4 to OUT4B			MAP Ch123	4 to OUT4A	

Bit D15	ENABLE	52
		-

This bit enables bits D[7:0] of register 52h.

Bits D	[14:8]	Must	write	'0
				_

Bits D[7:4] MAP_Ch1234_to_OUT4B

These bits set the OUT4B pin pair to the channel data mapping selection.

Bits D[3:0] MAP_Ch1234_to_OUT4A

These bits set the OUT4A pin pair to the channel data mapping selection.

Register 53h

D15	D14	D13	D12	D11	D10	D9	D8
ENABLE 53	0	0	0		MAP_Ch5678	3_to_OUT6B	
D7	D6	D5	D4	D3	D2	D1	D0
	MAP_Ch567	8_to_OUT5A			MAP_Ch5678	3_to_OUT5B	

Bit D15 ENABLE 53

This bit enables bits D[11:0] of register 53h.

Bits D[14:12] Must write '0'

Bits D[11:8]MAP_Ch5678_to_OUT6BThese bits set the OUT6B pin pair to the channel data mapping selection.Bits D[7:4]MAP_Ch5678_to_OUT5AThese bits set the OUT5A pin pair to the channel data mapping selection.

Bits D[3:0] MAP_Ch5678_to_OUT5B

These bits set the OUT5B pin pair to the channel data mapping selection.

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Register 54h

		DIZ	DTT	D10	D9	D8
0	0	0		MAP_Ch5678	3_to_OUT7A	
D6	D5	D4	D3	D2	D1	D0
MAP_Ch5678	B_to_OUT7B			MAP_Ch5678	3_to_OUT6A	
	0 D6 MAP_Ch5678	0 0 D6 D5 MAP_Ch5678_to_OUT7B	0 0 0 D6 D5 D4 MAP_Ch5678_to_OUT7B	0 0 0 D6 D5 D4 D3 MAP_Ch5678_to_OUT7B ENABLE 54	0 0 0 MAP_Ch5678 D6 D5 D4 D3 D2 MAP_Ch5678_to_OUT7B MAP_Ch5678 MAP_Ch5678	0 0 MAP_Ch5678_to_OUT7A D6 D5 D4 D3 D2 D1 MAP_Ch5678_to_OUT7B MAP_Ch5678_to_OUT6A

Bit D15 ENABLE 54

This bit enables bits D[11:0] of register 54h.

Bits D[14:12] Must write '0'

Bits D[11:8] MAP_Ch5678_to_OUT7A

These bits set the OUT7A pin pair to the channel data mapping selection.

Bits D[7:4] MAP_Ch5678_to_OUT7B

These bits set the OUT7B pin pair to the channel data mapping selection.

Bits D[3:0] MAP_Ch5678_to_OUT6A

These bits set the OUT6A pin pair to the channel data mapping selection.

Register 55h

D15	D14	D13	D12	D11	D10	D9	D8
ENABLE 55	0	0	0	0	0	0	0
D7	D6	D5	D4	D3	D2	D1	D0
	MAP_Ch567	8_to_OUT8A			MAP_Ch567	8_to_OUT8B	

Bit D15 ENABLE 55

This bit enables bits D[7:0] of register 55h.

Bits D[14:8] Must write '0'

Bits D[7:4] MAP_Ch5678_to_OUT8A

These bits set the OUT8A pin pair to the channel data mapping selection.

Bits D[3:0] MAP_Ch5678_to_OUT8B

These bits set the OUT8B pin pair to the channel data mapping selection.

Custom Coefficient Registers

Registers 5Ah to 65h⁽¹⁾

D15	D14	D13	D12	D11	D10	D9	D8
EN_CUSTOM_ FILT_CH1	0	0	0		COEFFn_SE	T_CH1[11:0]	
D7	D6	D5	D4	D3	D2	D1	D0
			COEFFn_SE	T_CH1[11:0]			

(1) n = 0 to 11.

These registers are the custom coefficient registers for channel 1.

Bit D15 EN_CUSTOM_FILT_CH1

0 = Built-in coefficients are used	
1 = Enables custom coefficients t	o be used

Bits D[14:12] Must write '0'

Bits D[11:0] COEFF*n*_SET_CH1[11:0]

These bits set the custom coefficient *n* for the channel 1 digital filter.

Registers 66h to 71h⁽¹⁾

D15	D14	D13	D12	D11	D10	D9	D8
EN_CUSTOM_ FILT_CH2	0	0	0		COEFFn_SE	T_CH2[11:0]	
D7	D6	D5	D4	D3	D2	D1	D0
			COEFFn_SE	T_CH2[11:0]			

(1) n = 0 to 11.

These registers are the custom coefficient registers for channel 2.

Bit D15 EN_CUSTOM_FILT_CH2

0 = Built-in coefficients are used

1 = Enables custom coefficients to be used

Bits D[14:12] Must write '0'

Bits D[11:0] COEFF*n*_SET_CH2[11:0]

These bits set the custom coefficient *n* for the channel 2 digital filter.



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Registers 72h to 7Dh⁽¹⁾

D15	D14	D13	D12	D11	D10	D9	D8			
EN_CUSTOM_ FILT_CH3	0	0	0		COEFFn_SE	T_CH3[11:0]				
D7	D6	D5	D4	D3	D2	D1	D0			
	COEFFn SET CH3[11:0]									

(1) n = 0 to 11.

These registers are the custom coefficient registers for channel 3.

Bit D15 EN_CUSTOM_FILT_CH3

0 = Built-in coefficients are used1 = Enables custom coefficients to be used

Bits D[14:12] Must write '0'

Bits D[11:0] COEFF*n*_SET_CH3[11:0]

These bits set the custom coefficient *n* for the channel 3 digital filter.

Registers 7Eh to 89h⁽¹⁾

D15	D14	D13	D12	D11	D10	D9	D8			
EN_CUSTOM_ FILT_CH4	0	0	0	COEFFn_SET_CH4[11:0]						
D7	D6	D5	D4	D3	D2	D1	D0			
COEFFn_SET_CH4[11:0]										

(1) n = 0 to 11.

These registers are the custom coefficient registers for channel 4.

Bit D15 EN_CUSTOM_FILT_CH4

0 = Built-in coefficients are used

1 = Enables custom coefficients to be used

Bits D[14:12] Must write '0'

Bits D[11:0] COEFF*n*_SET_CH1[11:0]

These bits set the custom coefficient *n* for the channel 4 digital filter.



Registers 8Ah to 95h⁽¹⁾

D15	D14	D13	D12	D11	D10	D9	D8			
EN_CUSTOM_ FILT_CH5	0	0	0	COEFFn_SET_CH5[11:0]						
D7	D6	D5	D4	D3	D2	D1	D0			
COEFFn_SET_CH5[11:0]										

(1) n = 0 to 11.

These registers are the custom coefficient registers for channel 5.

Bit D15 EN_CUSTOM_FILT_CH5

0 = Built-in coefficients are used1 = Enables custom coefficients to be used

Bits D[14:12] Must write '0'

Bits D[11:0] COEFF*n*_SET_CH5[11:0]

These bits set the custom coefficient *n* for the channel 5 digital filter.

Registers 96h to A1h⁽¹⁾

D15	D14	D13	D12	D11	D10	D9	D8			
EN_CUSTOM_ FILT_CH6	0	0	0	COEFFn_SET_CH6[11:0]						
D7	D6	D5	D4	D3	D2	D1	D0			
COEFFn_SET_CH6[11:0]										

(1) n = 0 to 11.

These registers are the custom coefficient registers for channel 6.

Bit D15 EN_CUSTOM_FILT_CH6

0 = Built-in coefficients are used

1 = Enables custom coefficients to be used

Bits D[14:12] Must write '0'

Bits D[11:0] COEFF*n*_SET_CH6[11:0]

These bits set the custom coefficient *n* for the channel 6 digital filter.



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Registers A2h to ADh⁽¹⁾

D15	D14	D13	D12	D11	D10	D9	D8			
EN_CUSTOM_ FILT_CH7	0	0	0	COEFFn_SET_CH7[11:0]						
D7	D6	D5	D4	D3	D2	D1	D0			
COEFFn_SET_CH7[11:0]										

(1) n = 0 to 11.

These registers are the custom coefficient registers for channel 7.

Bit D15 EN_CUSTOM_FILT_CH7

0 = Built-in coefficients are used 1 = Enables custom coefficients to be used

Bits D[14:12] Must write '0'

Bits D[11:0] COEFF*n*_SET_CH7[11:0]

These bits set the custom coefficient *n* for the channel 7 digital filter.

Registers AEh to B9h⁽¹⁾

D15	D14	D13	D12	D11	D10	D9	D8			
EN_CUSTOM_ FILT_CH8	0	0	0	COEFFn_SET_CH8[11:0]						
D7	D6	D5	D4	D3	D2	D1	D0			
COEFFn_SET_CH8[11:0]										

(1) n = 0 to 11.

These registers are the custom coefficient registers for channel 8.

Bit D15 EN_CUSTOM_FILT_CH8

0 = Built-in coefficients are used

1 = Enables custom coefficients to be used

Bits D[14:12] Must write '0'

Bits D[11:0] COEFF*n*_SET_CH8[11:0]

These bits set the custom coefficient *n* for the channel 8 digital filter.



Bit D15

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Register BEh

D15	D14	D13	D12	D11	D10	D9	D8
EN_LVDS_ PROG	0	0	0	0	0	DELAY_DATA_R[1:0]	
D7	D6	D5	D4	D3	D2	D1	D0
DELAY_LCLK_R[2:0]			DELAY_D/	ATA_F[1:0]	D	ELAY_LCLK_F[2:	:0]

This bit enables LVDS edge delay programmability.

Bits D[14:10]	Must write '0'
Bits D[9:8]	Refer Table 22 for settings.
Bits D[7:5]	Refer Table 23 for settings.
Bits D[4:3]	Refer Table 22 for settings.
Bits D[2:0]	Refer Table 23 for settings.

Register F0h

D15	D14	D13	D12	D11	D10	D9	D8
EN_EXT_REF	0	0	0	0	0	0	0
D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	0	0

The EN_HIGH_ADDRS register bit (register 01h, bit D4) must be set to '1' to allow access to this register.

Bit D15 EN_EXT_REF

0 =Internal reference mode (default)

1 = External reference mode enabled; apply the reference voltages on the REFT and REFB pins

Bits D[14:0] Must write '0'



APPLICATION INFORMATION

THEORY OF OPERATION

The ADS5295 is a low-power, 8-channel, 12-bit analog-to-digital converter (ADC) with sample rates up to 100 MSPS that run off of a single 1.8-V supply. All eight channels simultaneously sample the analog inputs at the input clock rising edge. The sampled signal is sequentially converted by a series of small resolution stages, with the outputs combined in a digital correction logic block. At every clock edge, the sample propagates through the pipeline, resulting in a data latency of 12 clock cycles.

ANALOG INPUT

The analog input consists of a switched-capacitor-based, differential sample-and-hold architecture, as shown in Figure 46. This differential topology results in very good ac performance even for high input frequencies at high sampling rates. The INP and INM pins must be externally biased around a common-mode voltage of 0.95 V, available on the VCM pin. For a full-scale differential input, each input pin (INP, INN) must swing symmetrically between VCM + 0.5 V and VCM – 0.5 V, resulting in a 2-V_{PP} differential input swing. The input sampling circuit has a high 3-dB bandwidth that extends up to 500 MHz (measured from the input pins to the sampled voltage).



Figure 46. Analog Input Equivalent Circuit



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Drive Circuit Requirements

For optimum performance, the analog inputs must be driven differentially. This architecture improves the common-mode noise immunity and even-order harmonic rejection. A small resistor (5 Ω to 10 Ω) in series with each input pin is recommended to damp out ringing caused by package parasitics. The drive circuits in Figure 47 and Figure 48 show an R-C filter across the analog input pins. The purpose of the filter is to absorb the glitches caused by the opening and closing of the sampling capacitors. Figure 49 and Figure 50 show the differential input resistance and capacitance across frequency.



Figure 49. ADC Differential Input Resistance (R_{IN}) vs Frequency



Large- and Small-Signal Input Bandwidth

The small-signal bandwidth of the analog input circuit is high, approximately 500 MHz. When using an amplifier to drive the ADS5295, the total amplifier noise up to the small-signal bandwidth must be considered. The large-signal bandwidth of the device depends on the amplitude of the input signal. The ADS5295 supports a $2-V_{PP}$ amplitude for input signal frequencies up to 90 MHz. For higher frequencies, the amplitude of the input signal must be decreased proportionally. For example, at 180 MHz, the device supports a maximum $1-V_{PP}$ signal.



CLOCK INPUT

The ADS5295 can operate with both single-ended (CMOS) and differential input clocks (such as sine wave, LVPECL, and LVDS). Operating with a low-jitter differential clock is recommended for good SNR performance, especially at input frequencies greater than 30 MHz. In the differential mode, the clock inputs are internally biased to a 0.95-V common-mode voltage. While driving with an external LVPECL or LVDS driver, TI recommends ac-coupling the clock signals so that the clock pins are correctly biased to the common-mode voltage (0.95 V). To operate using a single-ended clock, connect a CMOS clock source to CLKP and tie CLKN to GND. The device automatically detects the presence of a single-ended clock without requiring any configuration and disables the internal biasing. Typical clock termination schemes are shown in Figure 51, Figure 52, Figure 53, and Figure 54.



Figure 51. Differential Sine-Wave Clock Driving Circuit



Figure 53. Differential LVDS Clock Driving Circuit



Figure 52. Differential LVPECL Clock Driving Circuit



Figure 54. Single-Ended Clock Driving Circuit



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EXTERNAL REFERENCE MODE OF OPERATION

For normal operation, the device requires two reference voltages (REFT and REFB) that are generated internally by default, as shown in Figure 55. The value of the reference voltage determines the actual ADC full-scale input voltage, as shown in Equation 1:

Full-Scale Input Voltage = $2 \times (V_{REFT} - V_{REFB})$



Figure 55. Reference Equivalent Circuit

Any error in the reference results in a deviation of the full-scale input range from its ideal value of 2.0 V_{PP} , as shown in Equation 2:

Error in Full-Scale Voltage = 2x [Error in (V_{REFT} - V_{REFB})]

The reference inaccuracy results in a gain error, which is defined as Equation 3:

Gain Error (%) = Error in Full-Scale Voltage × 100 Ideal Full-Scale Voltage

= 2x [Error in
$$(V_{REFT} - V_{REFB})] \times \frac{100}{2.0}$$
 (3)

To minimize the gain error, the internal reference voltages are trimmed to an accuracy of $\pm 1.5\%$ (or ± 30 mV). To obtain even lower gain error, the ADS5295 supports an external reference mode of operation. In this mode, the internal reference amplifiers are powered down and an external amplifier must force the reference voltages on the REFT and REFB pins. For example, this mode can be used to ensure that multiple ADS5295 chips in the system have nearly the same full-scale voltage.

To enable the external reference mode, set the register bits as shown in Table 8. These settings power down the internal reference amplifier and the two reference voltages can be forced directly on the REFT and REFB pins as $V_{REFT} = 1.45$ V and $V_{REFB} = 0.45$ V.

I

FUNCTION	EN_HIGH_ADDRS	EN_EXT_REF
External reference using the REFT, REFB pins	1	1

Because the internal reference amplifiers are powered down, the accuracy of the full-scale voltage is determined by the accuracy of ($V_{REFT} - V_{REFB}$), where V_{REFT} is the voltage forced on REFT and V_{REFB} is the voltage forced on REFB.

Note that although the nominal value of $(V_{REFT} - V_{REFB}) = 1.0$ V, ensure that:

 $[(V_{REFT} + V_{REFB}) / 2 = 0.950 \text{ V} \pm 50 \text{ mV}].$

(2)

(1)



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Figure 56 shows an example of driving the reference pins. The $1-\mu F$ bypass capacitor helps provide the switching current drawn by the REFT and REFB pins. The external amplifier must provide an average current of 5 mA or less at 100 MSPS. The performance in the external reference mode depends on the sampling speed. At low sampling speeds (20 MSPS), the performance is the same as that of an internal reference. At higher speeds, the performance degrades because of the effect of the parasitic bond-wire inductance of the REF pins. Figure 57 highlights the difference in SNR between the external and internal reference modes.



Figure 56. Driving Reference Inputs in External Reference Mode



Figure 57. SNR in Internal and External Reference Mode



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LOW-FREQUENCY NOISE SUPPRESSION

The low-frequency noise suppression (LFNS) mode is particularly useful in applications where good noise performance is desired in the low-frequency band of dc to 1 MHz. By setting this mode, the low-frequency noise spectrum band around dc is shifted to a similar band around $f_S / 2$ (or the Nyquist frequency). As a result, the noise spectrum from dc to approximately 1 MHz improves significantly, as shown in Figure 58, Figure 59, and Figure 60.

This function can be selectively enabled in each channel using the LFNS_CH register bits. Figure 58, Figure 59, and Figure 60 show the effect of this mode on the spectrum.



Figure 58. Full-Scale Input Amplitude

Figure 59. Spectrum (Zoomed) From DC to 1 MHz



Figure 60. Spectrum (Zoomed) in 1-MHz Band from 49 MHz to 50 MHz (f_s = 100 MSPS)



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DIGITAL PROCESSING BLOCKS

The ADS5295 integrates a set of commonly-used digital functions that can be used to ease system design. These functions are shown in Figure 61 and are described in the following sections.



Figure 61. Digital Processing Block Diagram

Digital Gain

The ADS5295 includes programmable digital gain settings from 0 dB to 12 dB in 1-dB steps. The benefit of digital gain is obtaining improved SFDR performance. However, SFDR improvement is achieved at the expense of SNR; for each gain setting, SNR degrades by approximately 1 dB. Therefore, the gain can be used to trade-off between SFDR and SNR.

For each gain setting, the supported analog input full-scale range scales proportionally, as shown in Table 9. After reset, the device comes up in 0-dB gain mode. To use other gain settings, program the GAIN_CH[3:0] register bits.

GAIN_CH[3:0]	DIGITAL GAIN (dB)	ANALOG FULL-SCALE INPUT (VPP)
0000	0	2
0001	1	1.78
0010	2	1.59
0011	3	1.42
0100	4	1.26
0101	5	1.12
0110	6	1
0111	7	0.89
1000	8	0.8
1001	9	0.71
1010	10	0.63
1011	11	0.56
1100	12	0.5
Other combinations	Do not use	—

Table 9. Analog Full-Scale Range Across Gains



Digital Filter

The digital processing block includes the option to filter and decimate the ADC data outputs digitally. Various filters and decimation rates are supported: decimation rates of 2, 4, and 8, and low-pass, high-pass, and band-pass filters are available.

The filters are internally implemented as 24-tap symmetric finite impulse response (FIR) filters (even-tap) using the predefined coefficients of Equation 4:

y(n) =

$$\left(\frac{1}{2^{11}}\right) \times \left[h0.x(n) + h1.x(n-1) + h2.x(n-2) + ... + h11.x(n-11) + h12.x(n-12) + ... + h1.x(n-22) + h0.x(n-23)\right]$$
(4)

Alternatively, some filters can be configured as 23-tap symmetric FIR filters (odd-tap), as described in Equation 5:

y(n) =

$$\frac{1}{2^{11}} \right] \times \left[h0.x(n) + h1.x(n-1) + h2.x(n-2) + ... + h10.x(n-10) + h11.x(n-11) + h10.x(n-12) + ... + h1.x(n-21) + h0.x(n-22)\right]$$
(5)

In Equation 4 and Equation 5, h0 through h11 are 12-bit, signed, twos complement representations of the coefficients (-2048 to +2047). x(n) is the filter input data sequence and y(n) is the filter output sequence.

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Details of the registers used for configuring the digital filters are described in the digital filter registers (registers 29h, 2Eh, 2Fh, 30h, 31h, and 38h) and Table 10. Table 10 gives a summary of the register bits to be used for each filter type.

DECIMATION	TYPE OF FILTER	DATA_ RATE	DEC_RATE _CHn ⁽¹⁾	FILTER_ TYPE_CHn	ODD_ TAP_CH <i>n</i>	USE_ FILTER_ CH <i>n</i>	EN_ CUSTOM_ FILT_CH <i>n</i>	EN_DIG_ FILTER
Decimate-by-2	Built-in, low-pass, odd-tap filter (pass band = 0 to $f_S / 4$)	01	000	000	1	1	0	1
	Built-in, high-pass, odd-tap filter (pass band = 0 to $f_S / 4$)	01	000	001	1	1	0	1
	Built-in, low-pass, even-tap filter (pass band = 0 to $f_S / 8$)	10	001	010	0	1	0	1
	Built-in, first band pass, even-tap filter (pass band = $f_S / 8$ to $f_S / 4$)	10	001	011	0	1	0	1
Decimate-by-4	Built-in, second band pass, even-tap filter (pass band = $f_S / 4$ to 3 $f_S / 8$)	10	001	100	0	1	0	1
	Built-in, high-pass, odd-tap filter (pass band = $3 f_S / 8 \text{ to } f_S / 2$)	10	001	101	1	1	0	1
Decimate-by-2	Custom filter (user-programmable coefficients)	01	000	000	0 or 1	1	1	1
Decimate-by-4	Custom filter (user-programmable coefficients)	10	001	000	0 or 1	1	1	1
Decimate-by-8	Custom filter (user-programmable coefficients)	11	100	000	0 or 1	1	1	1
12-tap filter without decimation	Custom filter (user-programmable coefficients)	00	011	000	0	1	1	1

Table 10. Digital Filters

(1) The DEC_RATE_CH*n* value must be the same for all channels.



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Predefined Coefficients

The built-in filter types (low pass, high pass, and band pass) use predefined coefficients. The frequency response of the built-in filters is shown in Figure 62 and Figure 63.





Figure 63. Filter Response (Decimate-by-4)

The predefined coefficients for the decimate-by-2 and decimate-by-4 filters are listed in Table 11 and Table 12, respectively.

	DECIMATE-BY-2				
COEFFICIENTS	LOW-PASS FILTER	HIGH-PASS FILTER			
h0	3	-22			
h1	0	-65			
h2	5	-52			
h3	1	30			
h4	-27	66			
h5	-2	-35			
h6	73	-107			
h7	3	38			
h8	-178	202			
h9	-4	-41			
h10	636	-644			
h11	1024	1061			

Table 11. Predefined Coefficients for Decimate-by-2 Filters

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-62

-97

310

-501

575

(6)

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Table 12. Predefined Coefficients for Decimate-by-4 Filters									
		DECIMATE-BY-4							
COEFFICIENTS	LOW-PASS FILTER	1st BAND-PASS FILTER	2nd BAND-PASS FILTER	HIGH-PASS FILTER					
h0	-17	-7	-34	40					
h1	-50	19	-34	-15					
h2	71	-47	-101	-95					
h3	46	127	43	22					
h4	24	73	58	-8					
h5	-42	0	-28	-81					
h6	-100	86	-5	106					

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h7 h8

h9

h10

h11

Custom Filter Coefficients

In addition to the built-in filters described in the Predefined Coefficients section, customers also have the option of using their own custom, 12-bit, signed coefficients. Because of the symmetric FIR implementation of the filters, only 12 coefficients can be specified with the configuration of Equation 4 or Equation 5. These coefficients (h0 to h11) must be configured in the custom coefficient registers as shown in Equation 6:

117

-190

-464

-113

526

-179

294

86

-563

352

Register Content = 12-Bit Signed Representation of (Real Coefficient Value $\times 2^{11}$)

-97

8

202

414

554

The 12 custom coefficients must be loaded into 12 separate registers for each channel (refer to the custom coefficient registers, 5Ah to B9h). The MSB bit of each coefficient register determines whether the built-in filters or custom filters are used. If the EN CUSTOM FILT MSB bit is reset to '0', then the built-in filter coefficients are used. Otherwise, the custom coefficients are used.

Custom Filter without Decimation

Another mode is available that enables the use of the digital filter without decimation. In this mode, the filter behaves similar to a 12-tap symmetric FIR filter, as shown in Equation 7:

y(n) =

$$\left[\frac{1}{2^{11}} \right] \times \left[h6.x(n) + h7.x(n-1) + h8.x(n-2) + h9.x(n-3) + h10.x(n-4) + h11.x(n-5) + h11.x(n-6) + h10.x(n-7) + h9.x(n-8) + h8.x(n-9) + h7.x(n-10) + h6.x(n-11) \right]$$
(7)

In Equation 7, h6 through h11 are 12-bit, signed, twos complement representations of the coefficients (-2048 to +2047). x(n) is the filter input data sequence and y(n) is the filter output sequence.

In this mode, because the filter is implemented as a 12-tap symmetric FIR, only six custom coefficients must be specified and loaded in registers h6 to h11 (refer to the custom coefficient registers, 5Ah to B9h). To enable this mode, use the register setting specified in bit 15 of registers AEh to B9h.

Digital High-Pass Filter

In addition to the 12 tap filters described previously, the digital processing block also includes a separate highpass filter for each channel. The high-pass corner frequency can be programmed using bits D[14:10] in register 2Eh.



Digital Averaging

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The ADS5295 includes an averaging function where the ADC digital data from two (or four) channels can be averaged. The averaged data are output on specific LVDS channels. Table 13 shows the combinations of the input channels that can be averaged and the LVDS channels on which the averaged data are available.

AVERAGED CHANNELS	OUTPUT WHERE AVERAGED DATA ARE AVAILABLE AT	REGISTER SETTINGS
1, 2	OUT1A, OUT1B	Set AVG_OUT1 = 10 and EN_CHANNEL_AVG = 1
1, 2	OUT3A, OUT3B	Set AVG_OUT3 = 11 and EN_CHANNEL_AVG = 1
3, 4	OUT4A, OUT4B	Set AVG_OUT4 = 10 and EN_CHANNEL_AVG = 1
3, 4	OUT2A, OUT2B	Set AVG_OUT2 = 11 and EN_CHANNEL_AVG = 1
1, 2, 3, 4	OUT1A, OUT1B	Set AVG_OUT1 = 11 and EN_CHANNEL_AVG = 1
1, 2, 3, 4	OUT4A, OUT4B	Set AVG_OUT4 = 11 and EN_CHANNEL_AVG = 1
5, 6	OUT5A, OUT5B	Set AVG_OUT5 = 10 and EN_CHANNEL_AVG = 1
5, 6	OUT7A, OUT7B	Set AVG_OUT7 = 11 and EN_CHANNEL_AVG = 1
7, 8	OUT8A, OUT8B	Set AVG_OUT8 = 10 and EN_CHANNEL_AVG = 1
7, 8	OUT6A, OUT6B	Set AVG_OUT6 = 11 and EN_CHANNEL_AVG = 1
5, 6, 7, 8	OUT5A, OUT5B	Set AVG_OUT5 = 11 and EN_CHANNEL_AVG = 1
5, 6, 7, 8	OUT8A, OUT8B	Set AVG_OUT8 = 11 and EN_CHANNEL_AVG = 1

Table 13. Using Channel Averaging

Performance with Digital Processing Blocks

In applications where higher SNR performance is desired, digital processing blocks (such as averaging and decimation filters) can be used advantageously to achieve this. Table 14 shows the improvement in SNR that can be achieved compared to the default value, using these modes.

Table 14. SNR Improvement Using Digital Processing

MODE ⁽¹⁾	TYPICAL SNR (dB) ⁽²⁾	TYPICAL IMPROVEMENT IN SNR (dB)
Default	70.6	NA
With decimate-by-2 filter enabled	74.64	4.04
With decimate-by-4 filter enabled	76.13	5.53
With decimate-by-8 filter enabled	77.04	6.44
With two channels averaged and decimate-by-4 filter enabled	77.43	6.83
With four channels averaged	76.14	5.54
With four channels averaged and decimate-by-4 filter enabled	79.27	8.67

(1) Custom coefficients are used for the decimate-by-8 filter.

(2) In all these modes (except the default one), 14x serialization is used to capture data.



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PROGRAMMABLE MAPPING BETWEEN INPUT CHANNELS AND OUTPUT PINS

The ADS5295 has 16 pairs of LVDS channel outputs. The mapping of ADC channels to LVDS output channels is programmable to allow for flexibility in board layout. The control register mapping is shown in Table 15. The 16 LVDS channel outputs are split into two groups of eight LVDS pairs. Within each group, four ADC input channels can be multiplexed to the eight LVDS pairs, depending on the mode of operation (one-wire mode or two-wire mode).

ADDRESS (Hex)	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	NAME
	1												Х	Х	Х	Х	MAP_CH1234_TO_OUT1A
50	1								х	Х	х	Х					MAP_CH1234_TO_OUT1B
	1				Х	Х	Х	Х									MAP_CH1234_TO_OUT2A
	1												Х	Х	Х	Х	MAP_CH1234_TO_OUT2B
51	1								Х	Х	Х	Х					MAP_CH1234_TO_OUT3A
	1				Х	Х	Х	Х									MAP_CH1234_TO_OUT3B
50	1												Х	Х	Х	Х	MAP_CH1234_TO_OUT4A
52	1								Х	Х	Х	Х					MAP_CH1234_TO_OUT4B
	1												х	Х	Х	Х	MAP_CH5678_TO_OUT5B
53	1								Х	Х	Х	Х					MAP_CH5678_TO_OUT5A
	1				Х	Х	Х	Х									MAP_CH5678_TO_OUT6B
	1												Х	Х	Х	Х	MAP_CH5678_TO_OUT6A
54	1								Х	Х	Х	Х					MAP_CH5678_TO_OUT7B
	1				Х	Х	Х	Х									MAP_CH5678_TO_OUT7A
EE	1												Х	Х	Х	Х	MAP_CH5678_TO_OUT8B
55	1								Х	Х	Х	Х					MAP_CH5678_TO_OUT8A

Table 15. Mapping Control Registers

Input channels 1 to 4 can be mapped to any LVDS output (OUT1A, OUT1B to OUT4A, OUT4B) using the MAP_CH1234_TO_OUTnA, MAP_CH1234_TO_OUTnB bits, as shown in Table 16.

MAP_CH1234_TO_OUTN[3:0] ⁽¹⁾	MAPPING	USED IN ONE-WIRE MODE?	USED IN TWO-WIRE MODE?
0000	ADC input channel IN1 to OUTn	Y	Y (LSB byte)
0001	ADC input channel IN1 to OUT <i>n</i> (two-wire only)	Ν	Y (MSB byte)
0010	ADC input channel IN2 to OUTn	Y	Y (LSB byte)
0011	ADC input channel IN2 to OUT <i>n</i> (two-wire only)	Ν	Y (MSB byte)
0100	ADC input channel IN3 to OUTn	Y	Y (LSB byte)
0101	ADC input channel IN3 to OUT <i>n</i> (two-wire only)	Ν	Y (MSB byte)
0110	ADC input channel IN4 to OUTn	Y	Y (LSB byte)
0111	ADC input channel IN4 to OUT <i>n</i> (two-wire only)	Ν	Y (MSB byte)
1xxx	LVDS output buffer OUT <i>n</i> powered down	_	_

(1) n = 1A, 1B, 2A, 2B, 3A, 3B, 4A, or 4B.



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Similarly, input channels 5 to 8 can be mapped to any LVDS output (OUT5A, OUT5B to OUT8A, OUT8B) using the MAP_CH5678_TO_OUTnA, MAP_CH5678_TO_OUTnB bits, as shown in Table 17. Both multiplexing options are controlled by registers 50h to 55h. Channel mapping block diagrams for one-wire mode and two-wire mode are illustrated in Figure 64 and Figure 65, respectively.

MAP_CH5678_TO_OUTN[3:0] ⁽¹⁾	MAPPING	USED IN ONE-WIRE MODE?	USED IN TWO-WIRE MODE?
0000	ADC input channel IN8 to OUTn	Y	Y (LSB byte)
0001	ADC input channel IN8 to OUT <i>n</i> (two-wire only)	Ν	Y (MSB byte)
0010	ADC input channel IN7 to OUTn	Y	Y (LSB byte)
0011	ADC input channel IN7 to OUT <i>n</i> (two-wire only)	Ν	Y (MSB byte)
0100	ADC input channel IN6 to OUTn	Y	Y (LSB byte)
0101	ADC input channel IN6 to OUT <i>n</i> (two-wire only)	Ν	Y (MSB byte)
0110	ADC input channel IN5 to OUTn	Y	Y (LSB byte)
0111	ADC input channel IN5 to OUT <i>n</i> (two-wire only)	Ν	Y (MSB byte)
1xxx	LVDS output buffer OUT <i>n</i> powered down	_	_

Table 17.	Multip	lexing	IN5	to	IN8

(1) n = 5A, 5B, 6A, 6B, 7A, 7B, 8A, or 8B.



(1) For channels 1 to 4, n = 1A, 1B, 2A, 2B, 3A, 3B, 4A, and 4B. For channels 5 to 8, n = 5A, 5B, 6A, 6B, 7A, 7B, 8A, and 8B.

Figure 64. One-Wire Channel Mapping Mode



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(1) For channels 1 to 4, n = 1A, 1B, 2A, 2B, 3A, 3B, 4A, and 4B. For channels 5 to 8, n = 5A, 5B, 6A, 6B, 7A, 7B, 8A, and 8B.

Figure 65. Two-Wire Channel Mapping Mode

Channel 5 MSB Byte Data[15:8] MAP_CH5678_to_OUTn[3:0] = 0111


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The default mapping for the one-wire and two-wire modes is shown in Table 18 and Table 19, respectfully.

ANALOG INPUT CHANNEL	LVDS OUTPUT ⁽¹⁾
Channel IN1	OUT1A
Channel IN2	OUT2A
Channel IN3	OUT3A
Channel IN4	OUT4A
Channel IN5	OUT5A
Channel IN6	OUT6A
Channel IN7	OUT7A
Channel IN8	OUT8A

Table 18. Mapping for One-Wire Mode

(1) ADC data are only available on OUTnA with default register settings.

Table 19. Mapping for Two-Wire Mode

ANALOG INPUT CHANNEL	LVDS OUTPUT ⁽¹⁾
Channel IN1	OUT1A, OUT1B
Channel IN2	OUT2A, OUT2B
Channel IN3	OUT3A, OUT3B
Channel IN4	OUT4A, OUT4B
Channel IN5	OUT5A, OUT5B
Channel IN6	OUT6A, OUT6B
Channel IN7	OUT7A, OUT7B
Channel IN8	OUT8A, OUT8B

(1) ADC data are available on both OUTnA and OUTnB.



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SYNCHRONIZATION USING THE SYNC PIN

The SYNC pin can be used to synchronize the data output from channels within the same chip or from channels across multiple chips when decimation filters are used with a reduced output data rate. When decimation filters are used (if the decimate-by-2 filter is enabled, for example), then effectively, the device outputs one digital code for every two analog input samples. If the SYNC pulse is not used, then the filters are not synchronized (even within a chip). When the filters are not synchronized, one channel may be transmitting codes corresponding to input samples N, N+1, and so on, while another channel may be transmitting codes corresponding to N+1, N+2, and so on.

To achieve synchronization across multiple chips, the SYNC pulse must arrive at all ADS5295 chips at the same time (as shown in Figure 66). The ADS5295 generates an internal synchronization signal that resets the internal clock dividers used by the decimation filter. Using the SYNC signal in this way ensures that all channels output digital codes corresponding to the same set of input samples.

Synchronizing the filters using the SYNC pin is enabled by default. No register bits are required to be written. The TP_HARD_SYNC register bit must be reset to '0' for this mode to function properly. As shown in Figure 66, the SYNC rising edge can be positioned anywhere within the window. SYNC width must be at least one clock cycle.

In addition, SYNC can also be used to synchronize the RAMP test patterns across channels. In order to synchronize the test patterns, TP_HARD_SYNC must be set to '1'. Setting TP_HARD_SYNC to '1' actually disables the sync of the filters.



Figure 66. SYNC Timing Diagram

Synchronizing ADC Sampling Instants

Note that SYNC does not and cannot be used to synchronize the ADC sampling instants across chips. All channels within a single chip sample the analog inputs simultaneously. To ensure that channels across two chips sample the analog inputs simultaneously, the input clock must be routed to both chips with an identical length. This layout ensures that the input clocks arrive at both chips at the same time. Therefore, the SYNC pin cannot be used to synchronize the sampling instants because the input clock routing must be implemented during board design.



DIGITAL OUTPUT INTERFACE

SERIAL LVDS INTERFACE

The ADS5295 offers several flexible output options, making the device easy to interface to an application-specific integrated circuit (ASIC) or a field-programmable gate array (FPGA). Each option can be easily programmed using the serial interface. A summary of all available options is listed in Table 20 along with the default values after power-up and reset. Following Table 20, each option is described in detail. Table 21 lists the two-wire register settings for the LVDS interface.

		AVAILA	BLE IN:	DEFAULT AFTER	
FEATURE	OPTIONS	ONE- WIRE	TWO- WIRE	POWER-UP AND RESET	BRIEF DESCRIPTION
Wire interface	One- and two-wire	N	N	One-wire	One-wire: ADC data are sent serially over one pair of LVDS pins. Two-wire: ADC data are split and sent serially over two pairs of LVDS pins.
	12x	Y	Y	12x	
	10x	Y	Y	12x	
Serialization factor	14x	Y	Y		To be used with digital processing functions, such as averaging and decimation filers.
	16x	Y	Ν		To be used with digital processing functions, such as averaging and decimation filers.
DDR bit clock froquency	6x, 5x, 7x, 8x	Y	Ν	6x	Only available with one-wire interface for 12x, 10x, 14x, and 16x serialization factors, respectively.
DDR bit clock nequency	3x, 2.5x, 3.5x, 4x	Ν	Y	6x	Only available with two-wire interface for 12x, 10x, 14x, and 16x serialization factors, respectively.
Frame clock fraguency	1x sample rate	Y	Ν	1x	
Frame clock nequency	1/2x sample rate	Ν	Y	1x	
	Byte-wise	N	Y	Byte-wise	Only available with the two-wire interface. Byte-wise: the ADC data are split into upper and lower bytes that are output on separate wires.
Bit sequence	Bit-wise	N	Y	Byte-wise	Only available with the two-wire interface. Bit-wise: the ADC data are split into even and odd bits that are output on separate wires.
	Word-wise	Ν	Y	Byte-wise	Only available with the two-wire interface. Word-wise: successive ADC data samples are sent over separate wires.

Table 20. Summary of Output Interface Options

Table 21. Register Settings for Two-wire LVDS Interface

D15 (EN_WORD_BIT_WISE)	D8 (EN_BIT_WISE)	D[7:0] (EN_WORDWISE_BY_CH)	LVDS OUTPUT
0	х	Х	Byte-wise mode
1	х	1	Word-wise mode
1	1	0	Bit-wise mode

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One-Wire, 12x Serialization with DDR Bit Clock and 1x Frame Clock

The 12-bit ADC data are serialized and output over one LVDS pair per channel along with a 6x bit clock and a 1x frame clock, as shown in Figure 67. The output data rate is a 12x sample rate; therefore, it is suited for low sample rates.



(1) The upper data bit is the MSB-first mode data bit and the lower data bit is the LSB-first mode data bit.

Figure 67. LVDS Output Interface Timing Diagram (One-Wire, 12x Serialization)

One-Wire, 10x Serialization with DDR Bit Clock and 1x Frame Clock

The 10 upper bits of the 12-bit ADC data are serialized and output over one LVDS pair per channel along with a 5x bit clock and a 1x frame clock, as shown in Figure 68. The output data rate is a 10x sample rate; therefore, it is suited for low sample rates, typically up to 65 MSPS.



(1) The upper data bit is the MSB-first mode data bit and the lower data bit is the LSB-first mode data bit.

Figure 68. LVDS Output Interface Timing Diagram (One-Wire, 10x Serialization)



Two-Wire, 12x Serialization with DDR Bit Clock and 1/2x Frame Clock

The 12-bit ADC data are serialized and output over two LVDS pairs per channel, as shown in Figure 69 and Figure 70. The output data rate is a 12x sample rate with a 3x bit clock and a 1/2x frame clock. This interface can be used up to the maximum sample rate of the device because the output data rate is half of the data rate in the one-wire case.



- (1) The upper data bit is the MSB-first mode data bit and the lower data bit is the LSB-first mode data bit.
- (2) Shaded cells correspond to N+1 samples. Unshaded cells correspond to N samples.

Figure 69. LVDS Output Interface Timing Diagram (Two-Wire, 12x Serialization, Byte-Wise and Bit-Wise Modes)

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ADS5295





Figure 70. LVDS Output Interface Timing Diagram (Two-Wire, 12x Serialization, Word-Wise Mode)



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Two-Wire, 10x Serialization with DDR Bit Clock and 1/2x Frame Clock

The 10 upper bits of the 12-bit ADC data are serialized and output over two LVDS pairs per channel, as shown in Figure 71. The output data rate is a 5x sample rate per wire with a 2.5x bit clock and a 1/2x frame clock. This interface can be used up to the maximum sample rate of the device because the output data rate is half of the data rate in the one-wire case.



(1) The upper data bit is the MSB-first mode data bit and the lower data bit is the LSB-first mode data bit.

(2) Shaded cells correspond to N+1 samples. Unshaded cells correspond to N samples.

Figure 71. LVDS Output Interface Timing Diagram (Two-Wire, 10x Serialization)

When digital signal processing functions are used, the 14x and 16x serialization modes can also be used. These modes are:

- One-wire, 14x and 16x serialization with DDR bit clock and 1x frame clock mode, and
- Two-wire, 14x with DDR bit clock and 1/2x frame clock mode.

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PROGRAMMABLE LCLK PHASE

The ADS5295 enables the edge of the output bit clock (LCLK) to be programmed with the PHASE_DDR register bits. The default value of PHASE_DDR after reset is '10'. The default phase is shown in Figure 72.



Figure 72. Default LCLK Phase

The phase can also be changed by changing the value of the PHASE_DDR[1:0] bits, as shown in Figure 73.







PROGRAMMABLE LVDS OUTPUT CLOCK AND DATA EDGES

The ADS5295 enables the edges of the output data and output bit clock to be programmed with the DELAY_DATA and DELAY_LCLK register bits.

Figure 74 details the timing of the output data and clock edge movements. Table 22 and Table 23 show the register settings and corresponding delay values for the data and clock edge movements.





		DATA DELAY, RISING CLOCK EDGE			DATA DELAY, FALLING CLOCK EDGE
DELAY_D	ATA_R[1:0]	t _{DR} , Typical (ps)	DELAY_D	ATA_F[1:0]	t _{DF} , Typical (ps)
0	0	0	0	0	0
0	1	33	0	1	33
1	0	72	1	0	72
1	1	120	1	1	120

Table 22. LVDS Interface Output Data Delay Settings⁽¹⁾

(1) Delay settings are the same for both 10x and 12x serialization modes.

Table 23. LVDS Interface Output Clock Delay Settings⁽¹⁾

DEL	AY_LCLK	[_R[2:0]	CLOCK RISING EDGE DELAY t _{CR} , Typical (ps)	DELA	Y_LCLK_I	F[2:0]	CLOCK FALLING EDGE DELAY t _{CF} , Typical (ps)
0	0	0	0	0	0	0	0
0	0	1	33	0	0	1	33
0	1	0	72	0	1	0	72
0	1	1	120	0	1	1	120
1	0	0	106	1	0	0	106
1	0	1	159	1	0	1	159
1	1	0	202	1	1	0	202
1	1	1	244	1	1	1	244

(1) Delay settings are the same for both 10x and 12x serialization modes.



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LVDS OUTPUT DATA AND CLOCK BUFFERS

The equivalent circuit of each LVDS output buffer is shown in Figure 75. After reset, the buffer presents an output impedance of 100 Ω to match with the external 100- Ω termination.

The V_{DIFF} voltage is nominally 350 mV, resulting in an output swing of ± 350 mV with a 100- Ω external termination. The buffer output impedance behaves in the same way as a source-side series termination. By absorbing reflections from the receiver end, this impedance helps improve signal integrity.



(1) $R_{OUT} = 100 \Omega$.

Figure 75. LVDS Buffer Equivalent Circuit

OUTPUT DATA FORMAT

Two output data formats are supported: twos complement and offset binary. These formats can be selected by the BTC_MODE serial interface register bit. In the event of an input voltage overdrive, the digital outputs go to the appropriate full-scale level. For a positive overload, the 12-bit output data (D[11:0]) is FFFh in offset binary output format and 7FFh in twos complement output format. For a negative input overload, the output data is 000h in offset binary output format and 800h in twos complement output format.

BOARD DESIGN CONSIDERATIONS

Grounding

A single ground plane is sufficient to give good performance, provided the analog, digital, and clock sections of the board are cleanly partitioned. See the EVM User Guide (*ADS5295, 8-Channel ADC Evaluation Module,* SLAU442) for details on layout and grounding.

Supply Decoupling

Minimal external decoupling can be used without loss in performance because the ADS5295 already includes internal decoupling. Note that decoupling capacitors can help filter external power-supply noise; thus, the optimum number of capacitors would depend on the actual application. The decoupling capacitors should be placed very close to the converter supply pins.

Exposed Pad

In addition to providing a path for heat dissipation, the pad is also electrically connected to the digital ground internally. Therefore, the exposed pad must be soldered to the ground plane for best thermal and electrical performance.



DEFINITION OF SPECIFICATIONS

Analog Bandwidth: The analog input frequency at which the power of the fundamental is reduced by 3 dB with respect to the low-frequency value.

Aperture Delay: The delay in time between the rising edge of the input sampling clock and the actual time at which the sampling occurs. This delay is different across channels. The maximum variation is specified as aperture delay variation (channel-to-channel).

Aperture Uncertainty (jitter): The sample-to-sample variation in aperture delay.

Clock Pulse Width (duty cycle): The duty cycle of a clock signal is the ratio of the time that the clock signal remains at a logic high (clock pulse width) to the period of the clock signal. Duty cycle is typically expressed as a percentage. A perfect differential sine-wave clock results in a 50% duty cycle.

Maximum Conversion Rate: The maximum sampling rate at which specified operation is given. All parametric testing is performed at this sampling rate, unless otherwise noted.

Minimum Conversion Rate: The minimum sampling rate at which the ADC functions.

Differential Nonlinearity (DNL): An ideal ADC exhibits code transitions at analog input values spaced exactly 1 LSB apart. DNL is the deviation of any single step from this ideal value, measured in units of LSBs.

Integral Nonlinearity (INL): INL is the deviation of the ADC transfer function from a best-fit line determined by a least-squares curve fit of that transfer function, measured in units of LSBs.

Gain Error: Gain error is the deviation of the actual ADC input full-scale range from its ideal value. The gain error is given as a percentage of the ideal input full-scale range. Gain error has two components: error as a result of reference inaccuracy and error as a result of the channel. Both errors are specified independently as E_{GREF} and E_{GCHAN} , respectively. To a first-order approximation, the total gain error is ($E_{TOTAL} \sim E_{GREF} + E_{GCHAN}$). For example, if $E_{TOTAL} = \pm 0.5\%$, then the full-scale input varies from [(1 - 0.5 / 100) × FS_{IDEAL}] to [(1 + 0.5 / 100) × FS_{IDEAL}].

Offset Error: Offset error is the difference, given in number of LSBs, between the actual average ADC idle channel output code and the ideal average idle channel output code. This quantity is often mapped into millivolts.

Temperature Drift: The temperature drift coefficient (with respect to gain error and offset error) specifies the change per degree Celsius of the parameter from T_{MIN} to T_{MAX} . Drift is calculated by dividing the maximum deviation of the parameter across the T_{MIN} to T_{MAX} range by the difference of $T_{MAX} - T_{MIN}$.

Signal-to-Noise Ratio (SNR): SNR is the ratio of the power of the fundamental (P_S) to the noise floor power (P_N), excluding the power at dc and the first nine harmonics. SNR is either given in units of dBc (dB to carrier) when the absolute power of the fundamental is used as the reference, or dBFS (dB to full-scale) when the power of the fundamental is extrapolated to the converter full-scale range.

$$SNR = 10 \text{ Log}^{10} \frac{P_s}{P_N}$$

Signal-to-Noise and Distortion (SINAD): SINAD is the ratio of the power of the fundamental (P_S) to the power of all the other spectral components, including noise (P_N) and distortion (P_D), but excluding dc. SINAD is either given in units of dBc (dB to carrier) when the absolute power of the fundamental is used as the reference, or dBFS (dB to full-scale) when the power of the fundamental is extrapolated to the converter full-scale range.

$$SINAD = 10 \text{ Log}^{10} \frac{P_{\text{s}}}{P_{\text{N}} + P_{\text{D}}}$$
(9)

Effective Number of Bits (ENOB): ENOB is a measure of the converter performance as compared to the theoretical limit based on quantization noise.

$$\mathsf{ENOB} = \frac{\mathsf{SINAD} - 1.76}{6.02} \tag{10}$$

Total Harmonic Distortion (THD): THD is the ratio of the power of the fundamental (P_S) to the power of the first nine harmonics (P_D). THD is typically given in units of dBc (dB to carrier).

$$THD = 10 \text{ Log}^{10} \frac{P_{\text{S}}}{P_{\text{N}}}$$
(11)

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(8)

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Spurious-Free Dynamic Range (SFDR): SFDR is the ratio of power of the fundamental to the highest other spectral component (either spur or harmonic). SFDR is typically given in units of dBc (dB to carrier).

Two-Tone Intermodulation Distortion (IMD3): IMD3 is the ratio of the power of the fundamental (at frequencies f_1 and f_2) to the power of the worst spectral component at either frequency 2 $f_1 - f_2$ or 2 $f_2 - f_1$. IMD3 is either given in units of dBc (dB to carrier) when the absolute power of the fundamental is used as the reference, or dBFS (dB to full-scale) when the power of the fundamental is extrapolated to the converter full-scale range.

AC Power-Supply Rejection Ratio (AC PSRR): AC PSRR is the measure of rejection of variations in the supply voltage by the ADC. If ΔV_{SUP} is the change in supply voltage and ΔV_{OUT} is the resultant change of the ADC output code (referred to the input), then:

PSRR = 20 Log¹⁰ $\frac{\Delta V_{OUT}}{\Delta V_{SUP}}$ (Expressed in dBc)

(12)

Voltage Overload Recovery: The number of clock cycles taken to recover to less than 1% error after an overload on the analog inputs. This recovery is tested by separately applying a sine-wave signal with 6-dB positive and negative overload. The deviation of the first few samples after the overload (from the expected values) is noted.

Common-Mode Rejection Ratio (CMRR): CMRR is the measure of rejection of variation in the analog input common-mode by the ADC. If ΔV_{CM_IN} is the change in the common-mode voltage of the input pins and ΔV_{OUT} is the resulting change of the ADC output code (referred to the input), then:

CMRR = 20 Log¹⁰
$$\frac{\Delta V_{OUT}}{\Delta V_{CM}}$$
 (Expressed in dBc)

(13)

CROSSTALK: (only for multichannel ADCs) Crosstalk is a measure of the internal coupling of a signal from an adjacent channel into the channel of interest. Crosstalk is specified separately for coupling from the immediate neighboring channel (near-channel) and for coupling from a channel across the package (far-channel). Crosstalk is usually measured by applying a full-scale signal in the adjacent channel. Crosstalk is the ratio of the power of the coupling signal (as measured at the output of the channel of interest) to the power of the signal applied at the adjacent channel input. Crosstalk is typically expressed in dBc.



10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
ADS5295PFP	ACTIVE	HTQFP	PFP	80	96	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 85	ADS5295	Samples
ADS5295PFPR	ACTIVE	HTQFP	PFP	80	1000	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 85	ADS5295	Samples
ADS5295PFPT	ACTIVE	HTQFP	PFP	80	250	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 85	ADS5295	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

10-Dec-2020

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions a	are nominal
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Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ADS5295PFPR	HTQFP	PFP	80	1000	330.0	24.4	15.0	15.0	1.5	20.0	24.0	Q2



PACKAGE MATERIALS INFORMATION

5-Oct-2022



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
ADS5295PFPR	HTQFP	PFP	80	1000	350.0	350.0	43.0	

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TRAY



5-Oct-2022



Chamfer on Tray corner indicates Pin 1 orientation of packed units.

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	Unit array matrix	Max temperature (°C)	L (mm)	W (mm)	K0 (µm)	P1 (mm)	CL (mm)	CW (mm)
ADS5295PFP	PFP	HTQFP	80	96	6 x 16	150	315	135.9	7620	18.7	17.25	18.3

PFP (S-PQFP-G80)

PowerPAD™ PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

- C. Body dimensions do not include mold flash or protrusion
- D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com http://www.ti.com.
- E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.

F. Falls within JEDEC MS-026

PowerPAD is a trademark of Texas Instruments.



THERMAL PAD MECHANICAL DATA

PFP (S-PQFP-G80)

PowerPAD[™] PLASTIC QUAD FLATPACK

THERMAL INFORMATION

This PowerPAD[™] package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



NOTE: A. All linear dimensions are in millimeters

PowerPAD is a trademark of Texas Instruments





NOTES:

Α.

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All linear dimensions are in millimeters. Β. This drawing is subject to change without notice.

- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <http://www.ti.com>. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations. F. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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